

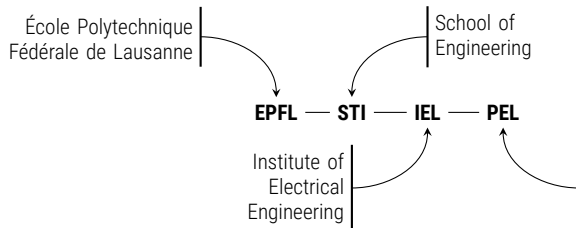
MEDIUM FREQ. TRANSFORMER DESIGN OPTIMIZATION FOR SOLID STATE TRANSFORMERS

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École Polytechnique Fédérale de Lausanne
Power Electronics Laboratory
Switzerland



POWER ELECTRONICS LABORATORY (PEL) AT EPFL



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Share:

Key Interests

- electrical energy generation, conversion, storage
- medium voltage applications
- high power electronic converters
- high performance variable speed drives
- modelling, simulation, design, optimization, control
- power semiconductors, advanced magnetics

CONTACT

Laboratory Director
Prof. Orsazan Dujic

Secretary
Marie Arisba

PEL Research Interests

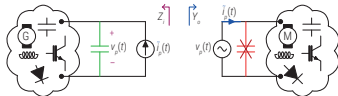
The research interests of the Power Electronics Laboratory are in the broad area of the Electrical Energy Generation, Conversion and Storage. In particular, we are interested into High Power Electronics Technologies for Medium Voltage applications, those operating with voltages in kV range, currents in kA range and powers in MW range. Power Electronics is one of the key-enabling technologies for the future energy systems, as it offers unprecedented flexibility for the integration and control of various electrical sources, storage elements or loads into the grid. This is equally valid for the present-day AC grids as well as for emerging concepts of DC grids, or inevitable mix of both in the near future.

To achieve controllable, reliable and efficient electrical energy conversion by means of advanced power electronic converters, we optimally use, but also influence and drive forward, advancements in different areas. These multidisciplinary considerations include: power semiconductors (e.g. Si, SiC, GaN), passive components (e.g. magnetics), insulation materials, mathematical modeling, simulations and optimization of power electronic systems, advanced control methods, etc.

PEL RESEARCH FOCUS

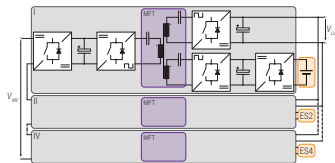
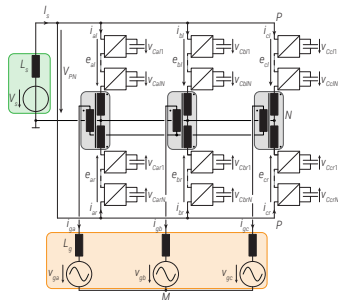
MVDC Technologies and Systems

- ▶ System Stability
- ▶ Protection Coordination
- ▶ Power Electronic Converters



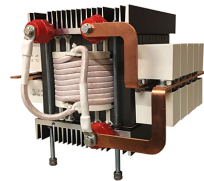
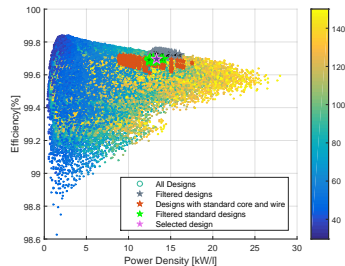
High Power Electronics

- ▶ Multilevel Converters
- ▶ Solid State Transformers
- ▶ Medium Frequency Conversion



Components

- ▶ Semiconductor devices
- ▶ Magnetics
- ▶ Characterization





INTRODUCTION and MOTIVATION

Why high power medium frequency transformers are important technology?

LINE FREQUENCY TRANSFORMERS

IEC 60076-1 definition - Power Transformer: *A static piece of apparatus with two or more windings which, by electromagnetic induction, transforms a system of alternating voltage and current into another system of voltage and current usually of different values and at the same frequency for the purpose of transmitting electrical power.*

Line Frequency Transformers

- ▶ Around for more than 100 of years
- ▶ Operated at low (grid) frequencies: 16.7Hz, 25Hz, 50/60Hz
- ▶ Standardized shapes and materials
- ▶ Cheap: $\approx 10\text{kUSD} / \text{MW}$
- ▶ Efficient: above 99 % for utility applications
- ▶ Simple and reliable device

What are the problems?

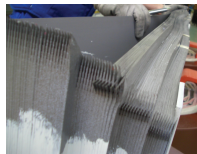
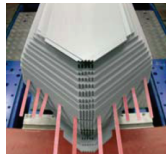
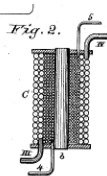
- ▶ Bulky - for certain applications
- ▶ Inefficient - for certain applications
- ▶ Uncontrollable power flow
- ▶ Fixed transformation (power, voltage, current, frequency)

UNITED STATES PATENT OFFICE.

LUCIEN GAULARD AND JOHN DIXON GIBBS, OF THE COUNTY OF MIDDLESEX, ENGLAND, ASSIGNORS TO GEORGE WESTINGHOUSE, JR., OF PITTSBURGH, PENNSYLVANIA.

SYSTEM OF ELECTRIC DISTRIBUTION.

SPECIFICATION forming part of Letters Patent No. 353,589, dated October 26, 1895.
Application filed March 6, 1894. Serial No. 39,439. (35 words.)



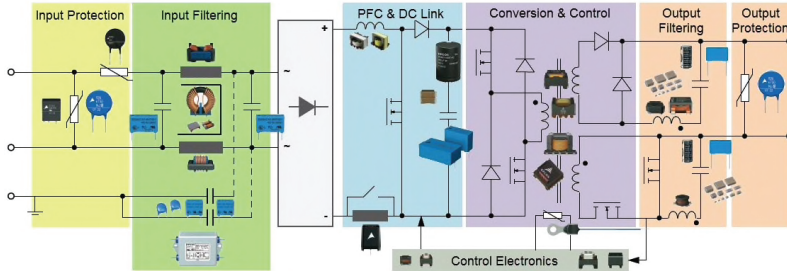
▲ Source: www.abb.com

MEDIUM-HIGH FREQUENCY CONVERSION

Switched Mode Power Supply (SMPS) Technologies

- ▶ Medium or High frequency conversion is not a new thing!
- ▶ Widely deployed in low voltage/power applications
- ▶ High efficiency
- ▶ Galvanic isolation at high frequency (standardized core sizes and shapes)
- ▶ Compact size (e.g. laptop chargers)
- ▶ Increased power density
- ▶ Cost savings

Could a Solid State Transformer provide that for a High Power Medium Voltage Applications?



▲ SMPS Technologies; Source: www.mouser.ch/new/tdk/epcos-smps/

SOLID STATE TRANSFORMERS

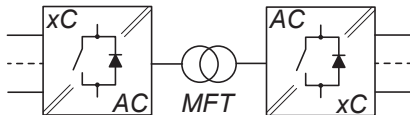
What is a Solid State Transformers?

- ▶ Not a transformer replacement?
- ▶ Should not be compared against 50/60 Hz transformer!

What is it?

- ▶ A converter
- ▶ A converter with galvanic isolation
- ▶ Can be designed for DC and AC (1-ph, 3-ph) grid
- ▶ Can be used in LV, MV and HV applications
- ▶ Can be made for AC-AC, DC-DC, AC-DC, DC-AC conversion
- ▶ Has power electronics on each terminal
- ▶ Transformer frequency higher than 50/60 Hz

Excellent tutorials are available at: <https://www.pes.ee.ethz.ch>



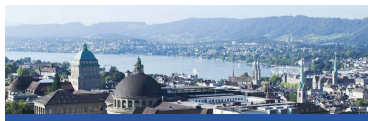
- ▲ Simplified SST concept

ETH zürich



Solid-State Transformers Key Design Challenges, Applicability, and Future Concepts

Johann W. Kolar, Jonas E. Huber
Power Electronics Laboratory
ETH Zurich, Switzerland



J. W. Kolar, J. E. Huber	Fundamentals and Application-Oriented Evaluation of Solid-State Transformer Concepts	Tutorial at the Southern Power Electronics Conference (SPEC 2016), Auckland, New Zealand, December 5-8, 2016
J. W. Kolar, J. E. Huber	Solid-State Transformers - Key Design Challenges, Applicability, and Future Concepts	Tutorial at the Internal Conference on Power Electronics and Motion Control (PEMC 2016), Varna, Bulgaria, September 29-30, 2016
J. W. Kolar, J. E. Huber	Solid-State Transformers - Key Design Challenges, Applicability, and Future Concepts	Tutorial at the 8th International Power Electronics and Motion Control Conference (PEMC 2016-IECE Asia), Hefei, China, May 22-26, 2016
J. W. Kolar, J. E. Huber	Solid-State Transformers: Key Design Challenges, Applicability, and Future Concepts	Tutorial at the Applied Power Electronics Conference (APPEC), Long Beach, CA, USA, Mar. 20-24, 2016
R. Buehler, J. W. Kolar	Advanced Modeling and Multi-Objective Optimization / Evaluation of SiC Converter Systems	Tutorial at the 3rd IEEE Workshop on Wide Bandgap Power Devices and Applications (WIPDA 2013), Blacksburg, VA, Nov. 1-5, 2013
R. Buehler, J. W. Kolar	Fundamentals and Multi-Objective Design of Inductive Power Transfer Systems	Tutorial at the 17th European Conference on Power Electronics and Applications (EPE 2013-ECCE Europe 2013), Geneva, Switzerland, September 8-10, 2013
R. Buehler, J. W. Kolar	Fundamentals and Multi-Objective Design of Inductive Power Transfer Systems	Tutorial at the 5th International Conference on Power Electronics (ICPE 2013-ECCE Asia), Seoul, Korea, June 1-5, 2013
R. Buehler, J. W. Kolar	Fundamentals and Multi-Objective Design of Inductive Power Transfer Systems	Tutorial at the Conference for Power Conversion and Intelligent Motion (PCIM Europe 2013), Nuremberg, Germany, May 19-21, 2013
J. W. Kolar, J. E. Huber	Solid-State Transformers in Future Traction and Smart Grids	Tutorial at the Conference for Power Conversion and Intelligent Motion (PCIM Europe 2013), Nuremberg, Germany, May 19-21, 2013
G. Ortiz, J. W. Kolar	Solid State Transformer Concepts in Traction and Smart Grid Applications	Seminar at the Conference for Power Electronics, Intelligent Motion, Power Quality (PCIM South America 2014), Sao Paulo, Brazil, October 14-15, 2014.

APPLICATIONS

Railway

- ▶ 1-phase AC grids [1]
- ▶ Few voltage levels: 15kV (16.7Hz) or 25kV (50Hz)
- ▶ Low frequency (historically): (15kV) 16.7Hz or (25kV) 50Hz
- ▶ On-board installations - serious space constraints
- ▶ Volume and Weight reduction - system savings
- ▶ Reliability - high number of devices?
- ▶ Efficiency - easy to beat traction LFT
- ▶ Control - similar to existing solutions
- ▶ Cost?



▲ ABB's PTT (Source: www.abb.com)

Utility

- ▶ 3-phase AC grids
- ▶ Many voltage levels: 3.3, 4.16, 6, 11, 15, 20kV, ...
- ▶ Grid frequency: 50Hz or 60Hz
- ▶ Sub-station installations - relatively low space constraints
- ▶ Volume and Weight reduction - not that relevant
- ▶ Reliability - even more complex due to 3-phases
- ▶ Efficiency - hard to beat distribution LFT
- ▶ Control - improved compared to existing solutions
- ▶ Cost?



▲ GE's SST [2] (Source: www.ge.com)

RAILWAY ON-BOARD ELECTRICAL SYSTEM

Railway on-board transformers:

- ▶ Step-down voltage to low levels
- ▶ Already optimized for low weight and volume
- ▶ Reduced efficiency as a price to pay
- ▶ Form factor depends on the mounting method
- ▶ Predominantly oil cooled / insulated
- ▶ Air cooled / solid insulation available as well

Few things to consider:

- ▶ 50Hz transformer is already fairly small
- ▶ 16.7Hz transformer is relatively bulky and inefficient
- ▶ Single galvanic isolation - insulation coordination
- ▶ Often, new train design defines the available space
- ▶ Design customization is common
- ▶ Power levels are modest and below 15MW
- ▶ Different from the utility transformers



▲ Various realization of traction transformers, Source: www.abb.com

RAILWAY SST

What traction SST offers in perspective:

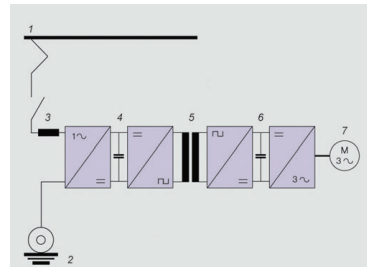
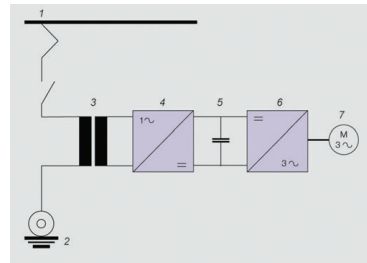
- ▶ Improved efficiency (specially for 15kV, 16.7Hz systems)
- ▶ Weight reduction - less raw materials
- ▶ Volume reduction - questionable due to insulation coordination
- ▶ Control features

Why is traction SST not out yet?

- ▶ Conservative traction market
- ▶ Lack of business case
- ▶ Reliability concerns
- ▶ Very hard to compete in 25kV, 50Hz grids
- ▶ Not a major performance increase
- ▶ Increased cost compared to state-of-the-art solutions

Prototypes

- ▶ ALSTOM
- ▶ ABB
- ▶ BOMBARDIER
- ▶ ...



▲ On-board traction system evolution with SST [1]

ABB - 1.2MW PETT

Characteristics

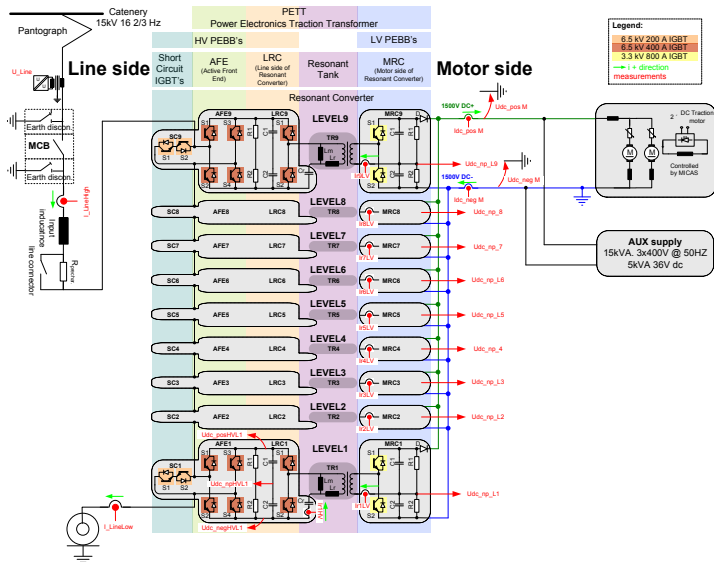
- ▶ 1-Phase MVAC to MVDC
- ▶ Power: 1.2MVA
- ▶ Input AC voltage: 15kV, 16.7Hz
- ▶ Output DC voltage: 1500 V
- ▶ 9 cascaded stages (n + 1)
- ▶ input-series output-parallel
- ▶ double stage conversion

99 Semiconductor Devices

- ▶ HV PEBB: 9 x (6 x 6.5kV IGBT)
- ▶ LV PEBB: 9 x (2 x 3.3kV IGBT)
- ▶ Bypass: 9 x (2 x 6.5kV IGBT)
- ▶ Decoupling: 9 x (1 x 3.3kV Diode)

9 MFTs

- ▶ Power: 150kW
- ▶ Frequency: 1.75kHz
- ▶ Core: Nanocrystalline
- ▶ Winding: Litz
- ▶ Insulation / Cooling: oil

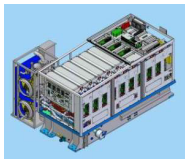


▲ ABB PETT scheme [3], [4]

ABB - 1.2MW PETT DESIGN

Retrofitted to shunting locomotive

- ▶ Replaced LFT + SCR rectifier
- ▶ Propulsion motor - 450kW
- ▶ 12 months of field service
- ▶ No power electronic failures
- ▶ Efficiency around 96%
- ▶ Weight: \approx 4.5 t



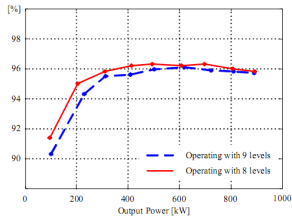
Technologies

- ▶ Standard 3.3kV and 6.5kV IGBTs
- ▶ De-ionized water cooling
- ▶ Oil cooling/insulation for MFTs
- ▶ n + 1 redundancy
- ▶ IGBTs used for bypass switch



Displayed at:

- ▶ Swiss Museum of Transport
- ▶ <https://www.verkehrshaus.ch>



▲ ABB PETT prototype [3], [4]

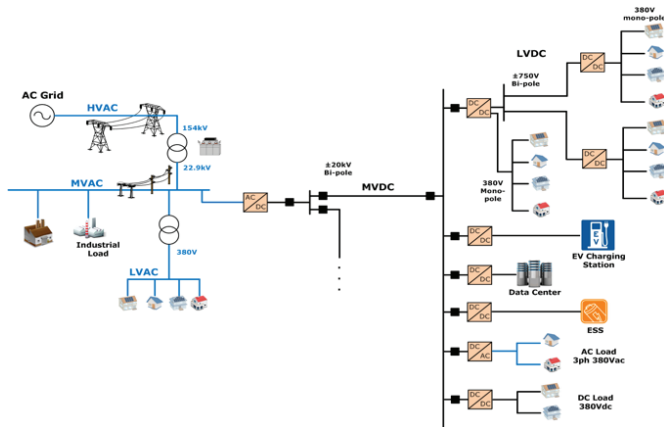
UTILITY SST

Quite different from railways

- ▶ 50 / 60 Hz grids
- ▶ Higher powers: MW, GW
- ▶ Much higher voltage: MV, HV
- ▶ High efficiency needed (> 99 %)
- ▶ High reliability needed
- ▶ High availability needed
- ▶ Weight may not be important
- ▶ Volume may not be important

Challenges

- ▶ Business case
- ▶ Cost
- ▶ Efficiency
- ▶ Reliability
- ▶ Availability



Design of a converter is the least problem!

▲ Possible future grid connections (www.english.hhi.co.kr)

SUMMARY - SOLID STATE TRANSFORMER

SST Pros

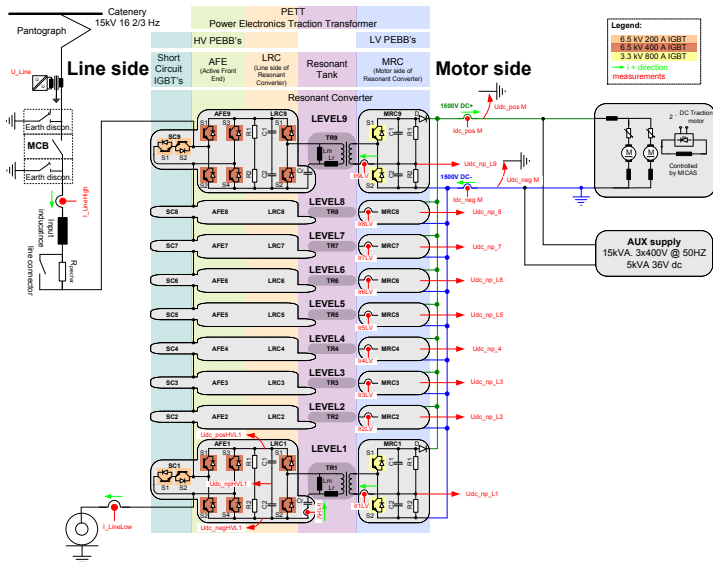
- ▶ Flexible grid interface
- ▶ AC-DC, AC-AC, DC-DC, DC-AC
- ▶ Galvanic isolation
- ▶ Advanced control features

SST Cons

- ▶ Compromised efficiency
- ▶ Increased complexity
- ▶ Higher cost
- ▶ Reliability
- ▶ Scalability

SST Future Research

- ▶ System level optimization
- ▶ Efficiency improvements
- ▶ Insulation coordination
- ▶ Protection
- ▶ MFT design optimization
- ▶ ...



▲ ABB PETT scheme: Not that simple...



MEDIUM FREQUENCY TRANSFORMERS

What are the design challenges?

MOTIVATION

- ▶ **Lower Volume** – easier system integration
- ▶ **Lower Weight** – especially important for onboard traction applications
- ▶ **Less Material** – lower investment cost, lower environmental footprint
- ▶ **Improved Efficiency** – application specific case
- ▶ **Modularity** – fractional power processing

$$A_p = \frac{P_t}{K_f K_u B_m J f}$$

size ↓

power ↓

↑ waveform ↑ insulation ↑ material ↑ cooling ↑ frequency

▲ Approximate transformer scaling relation



Three-phase 200-V, 5-kVA,
50-Hz Transformer

Single-phase, 250-V, 5-kVA,
20-kHz Transformer

▲ Example: frequency impact on the transformer size (Prof. Akagi)

WHICH ONE IS THE BEST MFT?

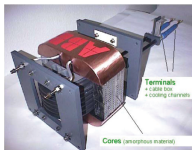


ABB: 350kW, 10kHz

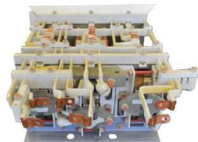
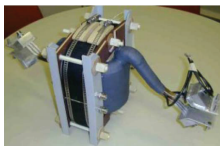
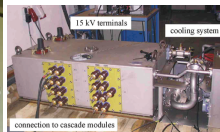


ABB: 3x150kW, 1.8kHz



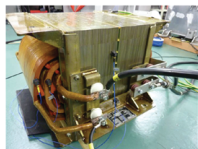
BOMBARDIER: 350kW, 8kHz



ALSTOM: 1500kW, 5kHz



IKERLAN: 400kW, 6kHz



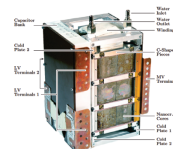
IKERLAN: 400kW, 600Hz



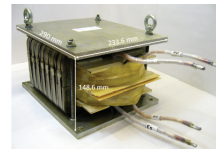
FAU-EN: 450kW, 5.6kHz



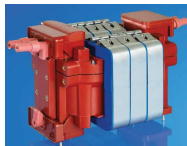
CHALMERS: 50kW, 5kHz



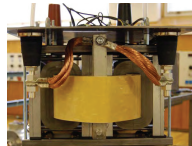
ETHZ: 166kW, 20kHz



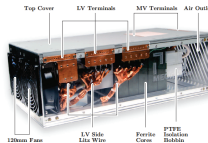
EPFL: 300kW, 2kHz



STS: 450kW, 8kHz



KTH: 170kW, 4kHz



ETHZ: 166kW, 20kHz



EPFL: 100kW, 10kHz

?

ACME: ???kW, ???kHz

DESIGN CONSTRAINTS

Electrical [1]

- ▶ Inductance
- ▶ $B < B_{sat}$
- ▶ Turns ratio
- ▶ Duty cycle
- ▶ Frequency
- ▶ $DCR < DCR_{max}$
- ▶ $J < J_{max}$
- ▶ Leakage inductance
- ▶ Self capacitance
- ▶ Self resonance
- ▶ Skin and Proximity effects
- ▶ EMI, EMC
- ▶ Shielding
- ▶ Efficiency
- ▶ Safety
- ▶ Isolation

Mechanical

- ▶ $A_{wdg} > A_{wdg-min}$
- ▶ Size (L, W, H)
- ▶ Volume
- ▶ Surface area
- ▶ Weight
- ▶ Safety
- ▶ Creepage distances
- ▶ Clearance distances
- ▶ Insulation class
- ▶ Materials
- ▶ Environmental

Thermal

- ▶ $T < T_{max}$
- ▶ $P_{wdq} < P_{wdg-max}$
- ▶ $P_{core} < P_{core-max}$
- ▶ Environmental

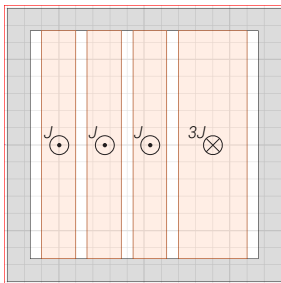
[1] Source: George Slama, Würth Elektronik, APEC2019 Educational Seminar

SKIN AND PROXIMITY EFFECT

Effects

- ▶ Non-uniform current density
- ▶ Under-utilization of the conductor material
- ▶ Localized H-field distortion within the conductor volume
- ▶ Impact on conduction losses
- ▶ Impact on leakage inductance

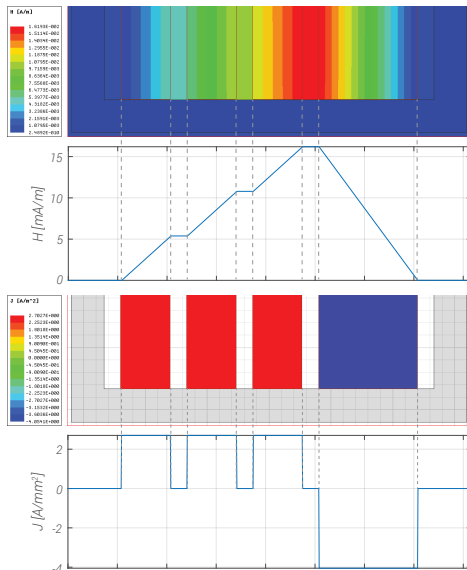
Example of the Foil Winding MFT Geometry Cross-Section



▲ Generic foil winding geometry

— 0.1 [Hz] ($\Delta = 0.01$)

* Δ - the penetration ratio



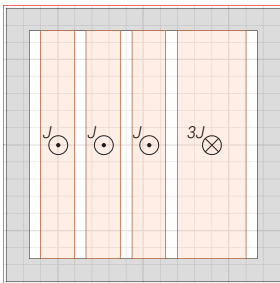
▲ H and J distribution within the core window area

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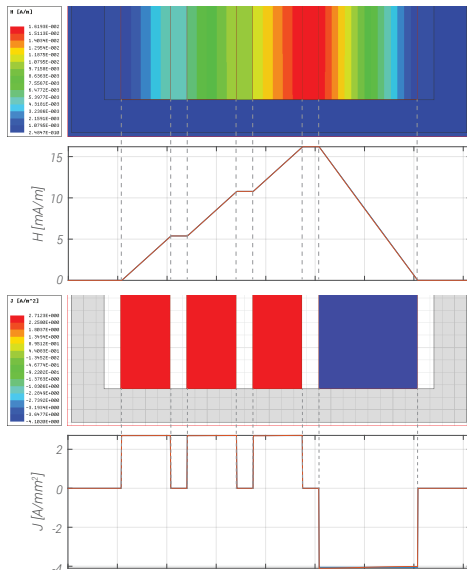
Example of the Foil Winding MFT Geometry Cross-Section



- 0.1 [Hz] ($\Delta = 0.01$)
- 100 [Hz] ($\Delta = 0.3$)

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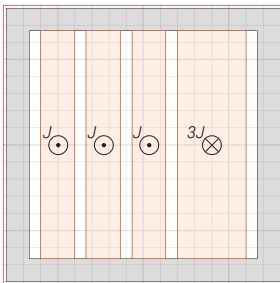
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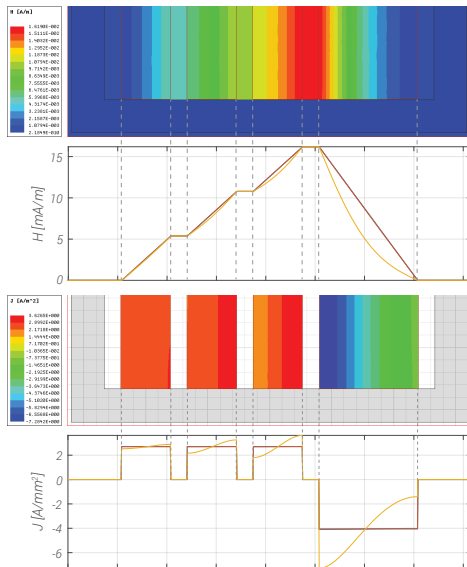
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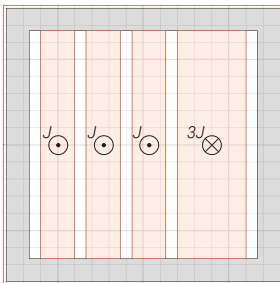
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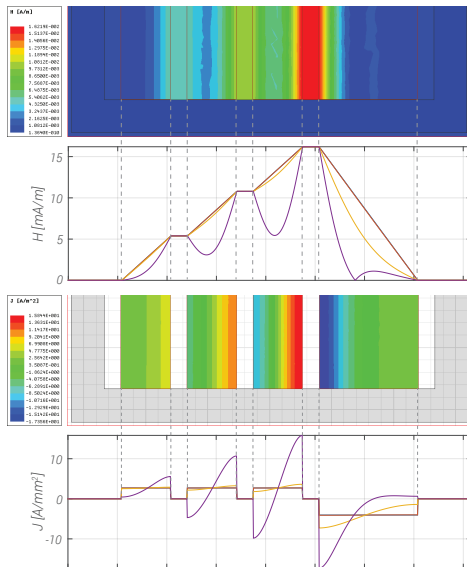
Example of the Foil Winding MFT Geometry Cross-Section



- 0.1 [Hz] ($\Delta = 0.01$)
- 100 [Hz] ($\Delta = 0.3$)
- 1000 [Hz] ($\Delta = 1$)
- 5000 [Hz] ($\Delta = 2.15$)

* Δ - the penetration ratio

▲ Generic foil winding geometry



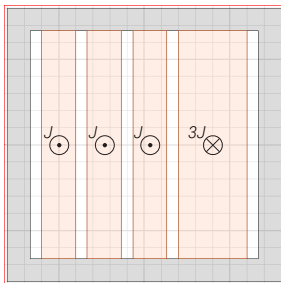
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- ▶ Impact on conduction losses
- ▶ Impact on leakage inductance

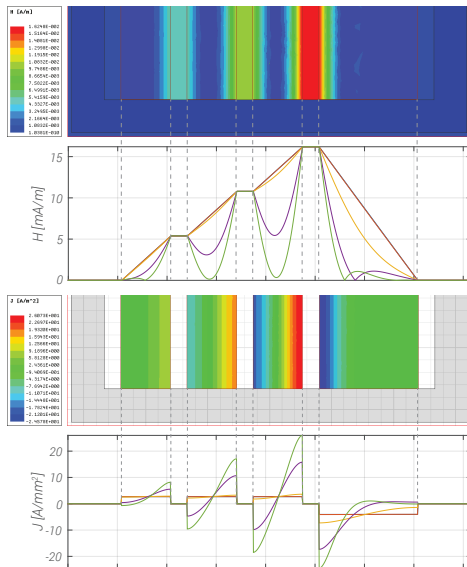
Example of the Foil Winding MFT Geometry Cross-Section



- 0.1 [Hz] ($\Delta = 0.01$)
- 100 [Hz] ($\Delta = 0.3$)
- 1000 [Hz] ($\Delta = 1$)
- 5000 [Hz] ($\Delta = 2.15$)
- 10000 [Hz] ($\Delta = 3$)

* Δ - the penetration ratio

▲ Generic foil winding geometry



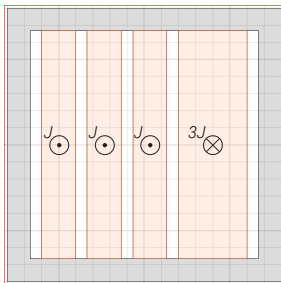
▲ H and J distribution within the core window area

SKIN AND PROXIMITY EFFECT

Effects

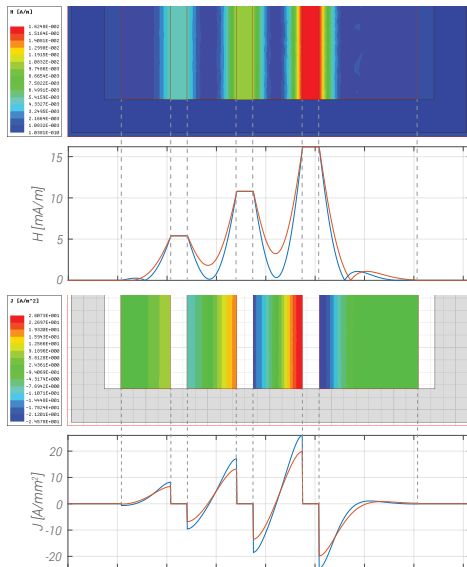
- ▶ Non-uniform current density
- ▶ Under-utilization of the conductor material
- ▶ Localized H-field distortion within the conductor volume
- ▶ Impact on conduction losses
- ▶ Impact on leakage inductance

Example of the Foil Winding MFT Geometry Cross-Section



▲ Generic foil winding geometry

— 10000 [Hz] (Cu)
— 10000 [Hz] (Al)

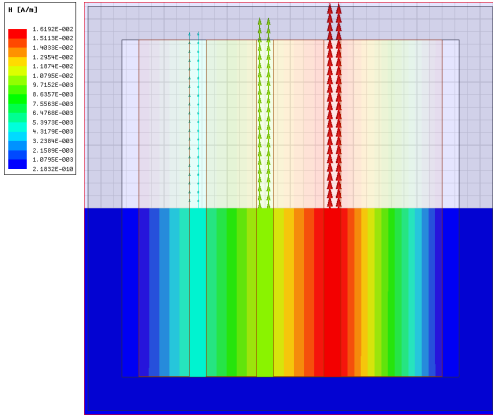


▲ H and J distribution within the core window area

EDGE EFFECT

MFT with fully filled core window height

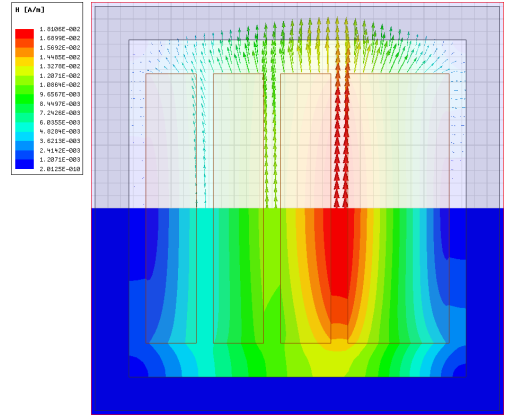
- ▶ Only H_y component exists
- ▶ H field is tangential to the foil surface



▲ Fully utilized core window height

MFT with 80% filled core window height

- ▶ Both H_x and H_y components exist
- ▶ H field is not tangential to the foil surface



▲ Partially utilized core window height

THERMAL COORDINATION

MFT Losses:

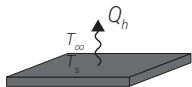
- ▶ Winding Losses
- ▶ Core Losses

Heat Transfer Mechanisms:

- ▶ Conduction



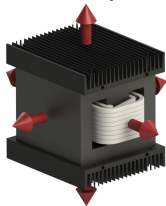
- ▶ Convection



- ▶ Radiation

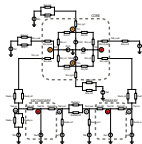


Qualitative Analysis:



$$Q_h \rightarrow R_m = \frac{l}{Ah} \rightarrow Q_h$$

Diagram showing thermal resistance $R_m = \frac{l}{Ah}$ between two temperatures T_1 and T_2 .



- ▶ Heat transfer

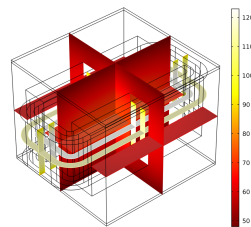
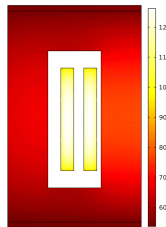
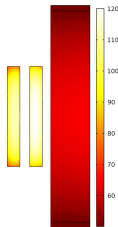
$$Q_h = hA\Delta T$$

- ▶ Temperature gradient

$$\Delta T = \frac{Q_h}{hA}$$

- ▶ Size decrease ($A \searrow$) implies $\Delta T \nearrow$

Temperature Distribution Example:



THERMAL COORDINATION (CONT.)

Core Materials:

- ▶ Thermal conductivity varies from 4Wm/K (ferrites) to 8.35Wm/K (Nanocrystalline)
- ▶ Isotropic thermal conductivity (e.g. ferrites)
- ▶ Anisotropic thermal conductivity (laminated cores e.g. Nanocrystalline)



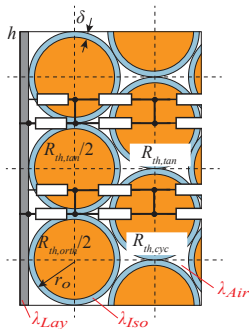
▲ Ferrite core - Isotropic



▲ Metglas core - Anisotropic

Windings:

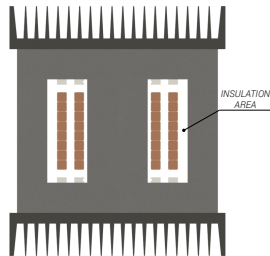
- ▶ Copper and Aluminum conductors combined with insulation
- ▶ Low R_{th} along the conductor path due to low R_{th} of Cu and Al
- ▶ High R_{th} in radial direction due to layers of insulation with high R_{th}



▲ Cross section of a round wire winding [5]

Winding insulation and cooling:

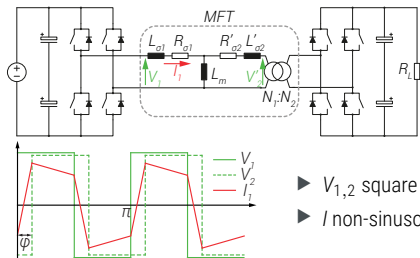
- ▶ Much higher insulation level requirement than within the winding insulation
- ▶ Good insulators have very low thermal conductivity (solid or fluid)
- ▶ Fluid based insulation provides much better cooling due to convection



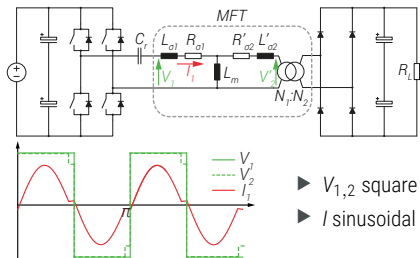
▲ MFT cross section area

NONSINUSOIDAL WAVEFORMS

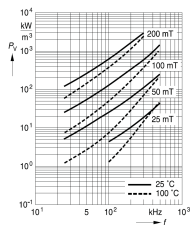
DAB Converter:



Series Resonant Converter:



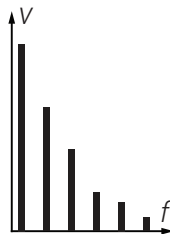
Core Losses:



▲ AC core losses

- ▶ Data-sheet data is for sinusoidal excitation
- ▶ Derived Steinmetz coefficients describe sinusoidal excitation losses
- ▶ Core is excited with square pulses
- ▶ Losses are effected
- ▶ Generalization of Steinmetz model

Winding Losses:

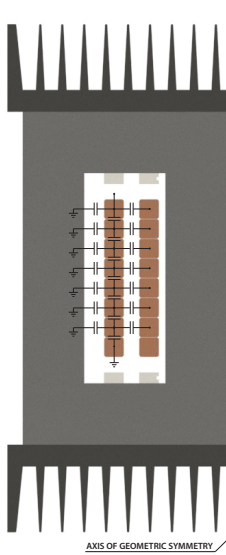


▲ Harmonics

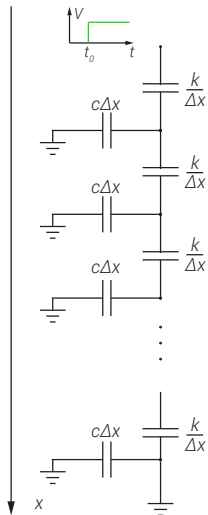
- ▶ Current waveform impacts the winding losses
- ▶ Copper is a linear material
- ▶ Losses can be evaluated in harmonic basis
- ▶ Current harmonic content must be evaluated
- ▶ Total losses are the sum of the individual harmonic losses

INSULATION COORDINATION

MFT Geometry Crosssection:

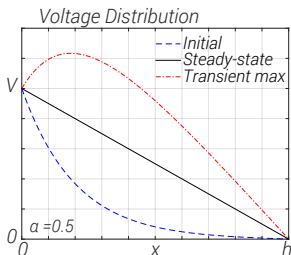


HF Winding Model:



MFT Electric Parameters:

- ▶ Parasitic capacitance cannot be neglected for HF
- ▶ Capacitances exist between turns, windings and core
- ▶ For pulse excitation voltage distribution is nonlinear
- ▶ Higher voltage gradient at the winding input than expected
- ▶ Damped oscillatory transient due to turn inductance
- ▶ Higher max voltage than expected during transient
- ▶ Need for overall insulation reinforcement
- ▶ Turn to turn insulation must especially be increased

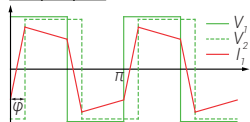
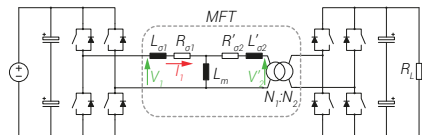


$$V(x) = V \frac{\sinh(ax)}{\sinh(ah)}$$

$$a = \sqrt{\frac{c}{k}}$$

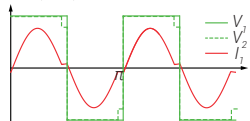
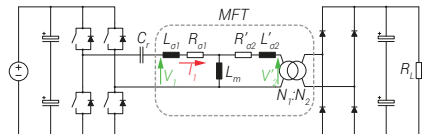
ACCURATE MFT ELECTRIC PARAMETER CONTROL

DAB Converter:



- ▶ $V_{1,2}$ square
- ▶ I non-sinusoidal

Series Resonant Converter:



- ▶ $V_{1,2}$ square
- ▶ I sinusoidal

DAB

- ▶ Leakage Inductance
- ▶ Controllability of the power flow
- ▶ Higher than $L_{\sigma.min}$:

$$L_{\sigma.min} = \frac{V_{DC1} V_{DC2} \varphi_{min} (\pi - \varphi_{min})}{2P_{out} \pi^2 f_s n}$$

- ▶ Magnetizing Inductance is normally high

SRC

- ▶ Leakage inductance is part of resonant circuit
- ▶ Must match the reference:

$$L_{\sigma.ref} = \frac{1}{\omega_0^2 C_r}$$

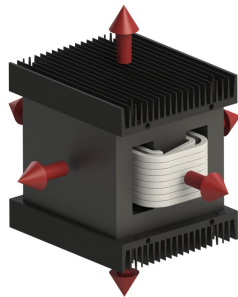
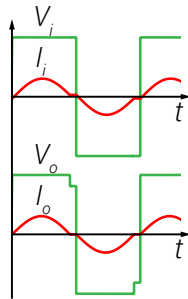
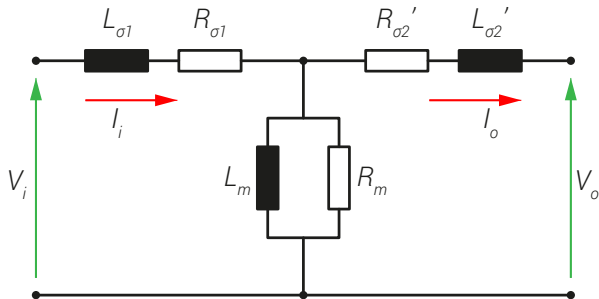
- ▶ Magnetizing inductance is normally high
- ▶ Reduced in case of LLC
- ▶ Limits the magnetization current to the reference $I_{m.ref}$
- ▶ Limits the switch-off current and losses

$$L_m = \frac{n V_{DC2}}{4 f_s I_{m.ref}}$$

- ▶ $I_{m.ref}$ has to be sufficiently high to maintain ZVS

MFT CHALLENGES - SUMMARY

- ▶ **Skin and proximity effect losses:** impact on efficiency and heating
- ▶ **Cooling:** increase of power density \Rightarrow decrease in size \Rightarrow less cooling surface \Rightarrow higher R_{th} \Rightarrow higher temperature gradients
- ▶ **Non-sinusoidal excitation:** impact on core and winding losses and insulation
- ▶ **Insulation:** coordination and testing taking into account high $\frac{dV}{dt}$ characteristic for power electronic converters
- ▶ **Accurate electric parameter control:** especially in case of resonant converter applications



▲ left: Transformer equivalent scheme; middle: typical waveforms for resonant operation; right: MFT heat evacuation issues



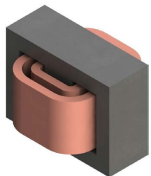
MATERIALS

What design choices are available?

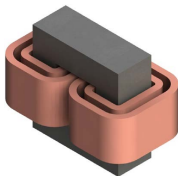
DESIGNS, TECHNOLOGIES, MATERIALS, ...

Construction Choices:

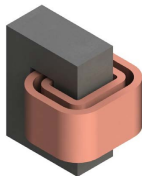
► MFT Types



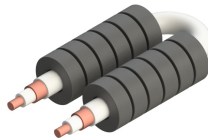
Shell Type



Core Type



C-Type



Coaxial Type

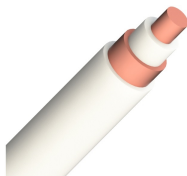
► Winding Types



Litz Wire



Foil



Coaxial



Hollow

Materials:

► Magnetic Materials

- Silicon Steel
- Amorphous
- Nanocrystalline
- Ferrites

► Windings

- Copper
- Aluminum

► Insulation

- Air
- Solid
- Oil

► Cooling

- Air natural/forced
- Oil natural/forced
- Water

MAGNETIC MATERIALS - SILICON STEEL

Ferromagnetic - Silicon Steel

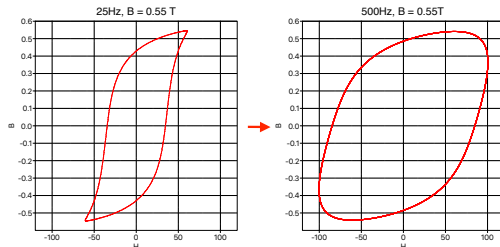
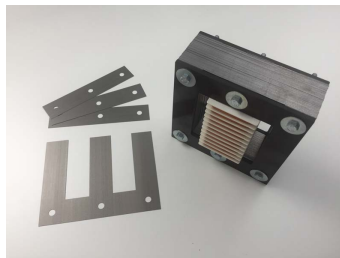
- ▶ Iron based alloy of Silicon provided as isolated laminations
- ▶ Mostly used for line frequency transformers

Advantages

- ▶ Wide initial permeability range
- ▶ High saturation flux density
- ▶ High Curie-temperature
- ▶ Relatively low cost
- ▶ Mechanically robust
- ▶ Various core shapes available (easy to form)

Disadvantages

- ▶ High hysteresis loss (irreversible magnetisation)
- ▶ High eddy current loss (high electric conductivity)
- ▶ Acoustic noise (magnetostriction)



▲ Example: Measured B-H curve of M330-35 laminate

Saturation B	Init. permeability	Core loss (10 kHz, 0.5T)	Conductivity
0.8 ~ 2.2 T	$0.6 \sim 100 \cdot 10^{-3}$	50 ~ 250 W/kg	$2 \cdot 10^7 \sim 5 \cdot 10^7$ S/m

MAGNETIC MATERIALS - AMORPHOUS ALLOY

Ferromagnetic - Amorphous Alloy

- ▶ Iron based alloy of Silicon as thin tape without crystal structure
- ▶ For both line frequency and switching frequency applications

Advantages

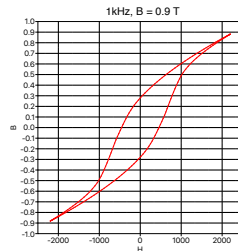
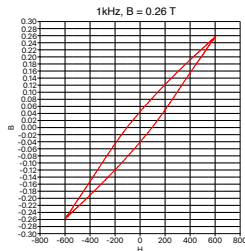
- ▶ High saturation flux density
- ▶ Low hysteresis loss
- ▶ Low eddy current loss (low electric conductivity)
- ▶ High Curie-temperature
- ▶ Mechanically robust

Disadvantages

- ▶ Relatively narrow initial permeability range
- ▶ Very high acoustic noise (magnetostriction)
- ▶ Limited core shapes available (difficult to form)
- ▶ Relatively expensive



Saturation B	Init. permeability	Core loss (10kHz, 0.5T)	Conductivity
0.5 ~ 1.6 T	$0.8 \cdot 10^3 \sim 50 \cdot 10^3$	2 ~ 20 W/kg	$< 5 \cdot 10^3$ S/m



▲ Example: Measured B-H curve of Metglas 2605SA

MAGNETIC MATERIALS - NANOCRYSTALLINE ALLOY

Ferromagnetic - Nanocrystalline Alloy

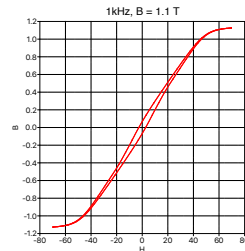
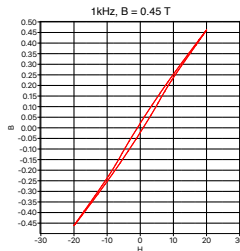
- ▶ Iron based alloy of silicon as thin tape with minor portion of crystal structure
- ▶ For both line frequency and switching frequency applications

Advantages

- ▶ Relatively narrow initial permeability range
- ▶ High saturation flux density
- ▶ Low hysteresis loss
- ▶ High Curie-temperature
- ▶ Low acoustic noise

Disadvantages

- ▶ Eddy current loss (compensated thanks to the thin tape)
- ▶ Mechanically fragile
- ▶ Limited core shapes available (difficult to form)
- ▶ Relatively expensive



▲ Example: Measured B-H curve of VITROPERM 500F

Saturation B	Init. permeability	Core loss (10kHz, 0.5T)	Conductivity
1 ~ 1.2 T	$0.5 \cdot 10^3 \sim 100 \cdot 10^3$	< 50 W/kg	$3 \cdot 10^3 \sim 5 \cdot 10^4$ S/m

MAGNETIC MATERIALS - FERRITES

Ferrimagnetic - Ferrites

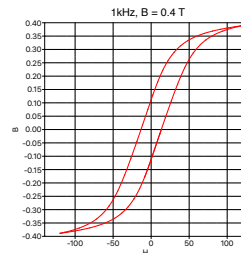
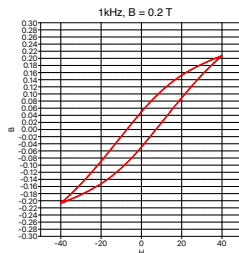
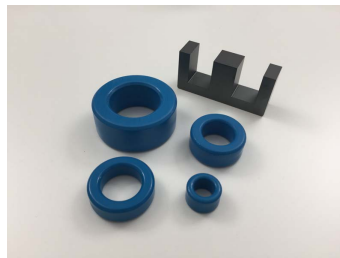
- ▶ Ceramic material made from powder of different oxides and carbons
- ▶ For both line frequency and switching frequency applications

Advantages

- ▶ Relatively narrow initial permeability range
- ▶ Low hysteresis loss
- ▶ Very low eddy current loss
- ▶ Low acoustic noise
- ▶ Relatively low cost
- ▶ Various core shapes available

Disadvantages

- ▶ Low saturation flux density
- ▶ Narrow range of initial permeability
- ▶ Magnetic properties deteriorate with temperature increase
- ▶ Mechanically fragile



▲ Example: Measured B-H curve of Ferrite N87

Saturation B	Init. permeability	Core loss (10kHz, 0.5T)	Conductivity
0.3 ~ 0.5 T	$0.1 \cdot 10^3 \sim 20 \cdot 10^3$	5 ~ 100 W/kg	$< 1 \cdot 10^{-5}$ S/m

MAGNETIC MATERIALS - CHARACTERIZATION

Material characterisation

- ▶ Data sheet are often not sufficient
- ▶ Power electronics = non-sinusoidal waveforms

Calorimetric approach

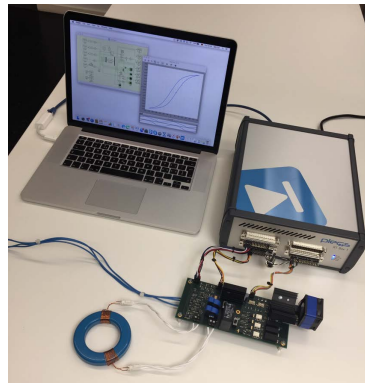
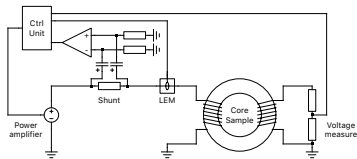
- ▶ Core sample placed in thermally isolated chamber
- ▶ Measure temperature difference between the inlet- and outlet coolant
- ▶ Time consuming and difficult to exclude winding loss

Electrical approach

- ▶ Two windings installed on the sample core
- ▶ RF Power amplifier provides sinusoidal on the primary winding
- ▶ Primary winding current sensing using shunt resistor, to obtain H
- ▶ Secondary winding voltage sensing using resistor divider, integrated to get B
- ▶ Control unit for reference signal generation and data acquisition



▲ Commercial B-H Analyser; Source: www.iti.iwatsu.co.jp/en



▲ EPFL characterisation setup for magnetic materials

WINDING MATERIALS

Copper winding

- ▶ Flat wire - low frequency, easy to use
- ▶ Litz wire - high frequency, limited bending
- ▶ Foil - provide flat windings
- ▶ Hollow tubes - provide cooling efficiency
- ▶ Better conductor
- ▶ More expensive
- ▶ Better mechanical properties

Copper Parameters

Electrical conductivity	$58.5 \cdot 10^6 \text{ S/m}$
Electrical resistivity	$1.7 \cdot 10^{-8} \Omega\text{m}$
Thermal conductivity	401 W/mK
TEC (from 0° to 100° C)	$17 \cdot 10^{-6} \text{ K}^{-1}$
Density	8.9 g/cm^3
Melting point	$1083 \text{ }^\circ\text{C}$

Aluminium winding

- ▶ Flat wire
- ▶ Foil - skin effect differences compared to Copper
- ▶ Hollow tubes
- ▶ Difficult to interface with copper
- ▶ Offer some weight savings
- ▶ Cheaper
- ▶ Somewhat difficult mechanical manipulations

Aluminum Parameters

Electrical conductivity	$36.9 \cdot 10^6 \text{ S/m}$
Electrical resistivity	$2.7 \cdot 10^{-8} \Omega\text{m}$
Thermal conductivity	237 W/mK
TEC (from 0° to 100° C)	$23.5 \cdot 10^{-6} \text{ K}^{-1}$
Density	2.7 g/cm^3
Melting point	$660 \text{ }^\circ\text{C}$

INSULATING MATERIALS

Multiple influencing factors

- ▶ Operating voltage levels
- ▶ Over-voltage category
- ▶ Environment - IP class
- ▶ Temperature
- ▶ Moisture
- ▶ Cooling implications
- ▶ Ageing (self-healing?)
- ▶ Manufacturing complexity
- ▶ Partial Discharge
- ▶ BIL
- ▶ Cost

Dielectric properties

- ▶ Breakdown voltage (dielectric strength)
- ▶ Permittivity
- ▶ Conductivity
- ▶ Loss angle
- ▶ ...

Dielectric material	Dielectric strength (kV/mm)	Dielectric constant
Air	3	1
Oil	5 - 20	2 - 5
Mica tape	60 - 230	5 - 9
NOMEX 410	18 - 27	1.6 - 3.7
PTFE	60 - 170	2.1
Mylar	80 - 600	3.1
Paper	16	3.85
PE	35 - 50	2.3
XLPE	35 - 50	2.3
KAPTON	118 - 236	3.9



▲ Variety of choices available...

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INSULATING MATERIALS - AIR

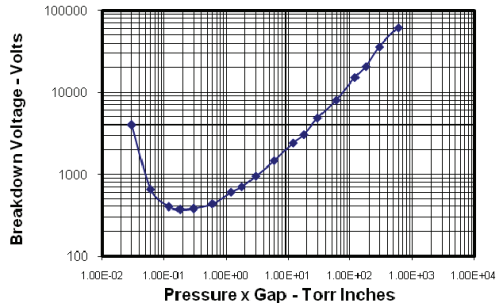
Air

- ▶ Generally good electric insulator
- ▶ Available
- ▶ Add no mass to design
- ▶ Free
- ▶ Provides cooling
- ▶ Not sufficient alone
- ▶ Additional insulation (e.g. turn-to-turn)
- ▶ Generally, not the smallest design
- ▶ Dielectric strength variation - **Pachen Law**

$$V_{BD} = \frac{Bpd}{\ln(Apd) - \ln\left(\ln\left(1 + \frac{1}{\gamma_{se}}\right)\right)}$$

- ▶ V_{BD} breakdown voltage in volts
- ▶ p - pressure in pascals
- ▶ d - gap distance in meters
- ▶ γ_{se} - secondary electron emission coef.
- ▶ A, B - parameters experimentally determined

Breakdown Voltage vs. Pressure x Gap
(Air)



▲ Paschen curve for air

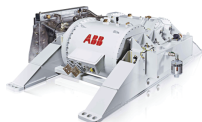
INSULATING MATERIALS - OIL

Oil

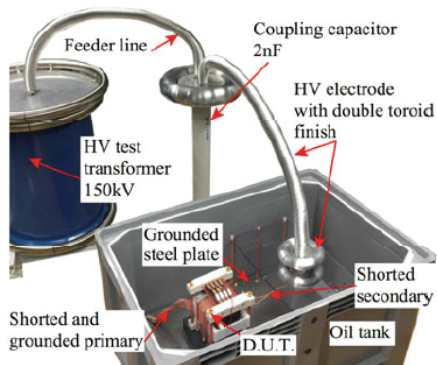
- ▶ In use for a very long time
- ▶ Excellent insulating properties
- ▶ Good thermal conductivity
- ▶ High voltage transformers
- ▶ Insulate and cool at the same time
- ▶ Natural or forced convection
- ▶ Self-healing (PD)
- ▶ Environmental concerns

Challenges

- ▶ Not a power electronics technology
- ▶ Integration issues
- ▶ Thermal expansion
- ▶ Forced convection - need for pump
- ▶ Flammability (mineral oils)
- ▶ Adds weight to the design
- ▶ Oil degradation



▲ left: Distribution oil transformer; right: New traction oil transformer; www.abb.com



▲ Oil insulated HFT PD testing [6]

INSULATING MATERIALS - SOLIDS

Solid Insulation

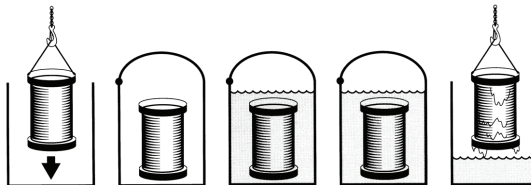
- ▶ Dry Type designs
- ▶ Vacuum-Pressure Impregnation (VPI)
- ▶ Vacuum-immersion (resin-encapsulated)
- ▶ Vacuum-fill (solid-cast)
- ▶ Variety of resin mixtures available
- ▶ Need for specialized equipment



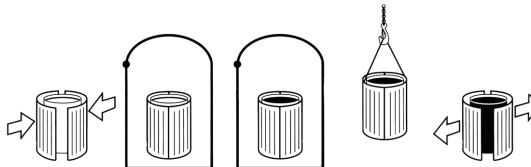
▲ left: www.sts-trafo.com; right: www.siemens.com

Challenges

- ▶ Direct impact on thermal design
- ▶ Adds weight to the design
- ▶ Ageing uncertainty
- ▶ Mixed frequency stress
- ▶ Partial Discharge
- ▶ Mechanical strength - cracks
- ▶ CTI - Creepage distances



▲ Resin-Encapsulated transformer winding (www.schneider-electric.com)



▲ Solid-Cast transformer winding (www.schneider-electric.com)

SUMMARY - TECHNOLOGIES AND MATERIALS

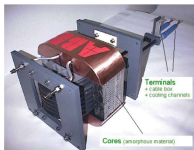


ABB: 350kW, 10kHz

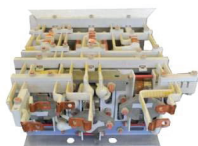
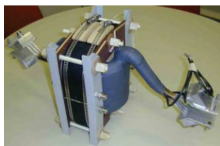
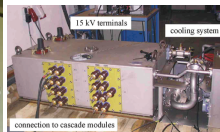


ABB: 3x150kW, 1.8kHz



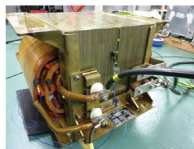
BOMBARDIER: 350kW, 8kHz



ALSTOM: 1500kW, 5kHz



IKERLAN: 400kW, 6kHz



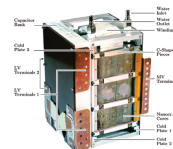
IKERLAN: 400kW, 600Hz



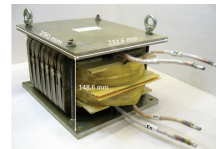
FAU-EN: 450kW, 5.6kHz



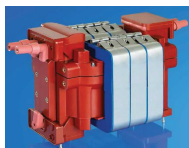
CHALMERS: 50kW, 5kHz



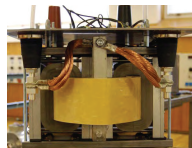
ETHZ: 166kW, 20kHz



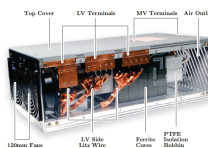
EPFL: 300kW, 2kHz



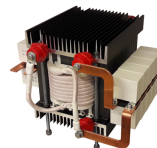
STS: 450kW, 8kHz



KTH: 170kW, 4kHz



ETHZ: 166kW, 20kHz



EPFL: 100kW, 10kHz

?

ACME: ???kW, ???kHz

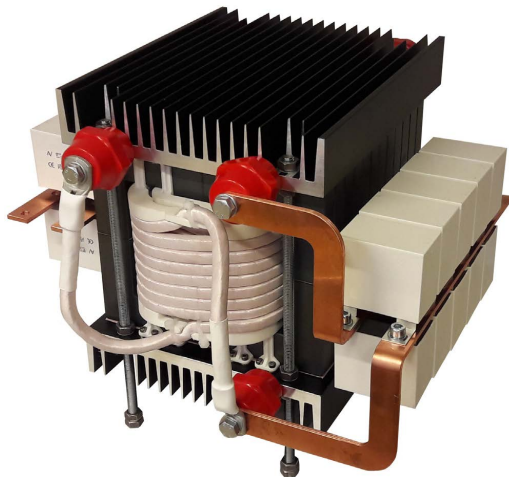


MFT MODELING

The underlying analytical descriptions?

MODELING: RELEVANT EFFECTS

- ▶ Core Losses
- ▶ Winding Losses
- ▶ Leakage Inductance
- ▶ Magnetizing Inductance
- ▶ Thermal Model



MODELING: CORE LOSSES

Different core loss models:

- ▶ Based on characterization of magnetic hysteresis [7], [8], [9]
- ▶ Based on loss separation [10]
- ▶ Time domain core loss model [11]
- ▶ Based on Steinmetz Equation (MSE [12], IGSE [13], iIGSE [14])

Original Steinmetz Equation:

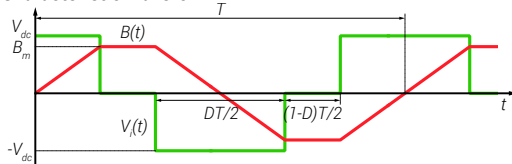
$$P_c = K f^a B_m^\beta$$

Improved Generalized Steinmetz Equation (IGSE):

$$P_c = \frac{1}{T} \int_0^T k_i \left| \frac{dB(t)}{dt} \right|^a (\Delta B)^{\beta-a} dt$$

$$k_i = \frac{K}{(2\pi)^{a-1} \int_0^{2\pi} |\cos(\theta)|^a 2^{\beta-a} d\theta}$$

Characteristic Waveform:



$$\left| \frac{dB(t)}{dt} \right| = \begin{cases} 0 & \text{for } (1-D)T \\ \frac{2\Delta B}{DT} & \text{for } DT \end{cases}$$

Application of IGSE on the Characteristic Waveform:

$$P_s = 2^{a+\beta} k_i f^a B_m^\beta D^{1-a}$$

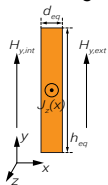
$$k_i = \frac{K}{2^{\beta-1} \pi^{a-1} \left(0.2761 + \frac{1.7061}{a+1.354} \right)}$$

MODELING: WINDING LOSSES

Foil Winding Electromagnetic Field Analysis:

- ▶ Dowell foil winding loss model [15]
- ▶ Porosity factor validity analysis [16], [17]
- ▶ Round wire winding loss model [18]
- ▶ ...

Foil Winding Electromagnetic Field Analysis:



$$H_y = H_{ext} \frac{\sinh(ax)}{\sinh(ad_{eq})} - H_{int} \frac{\sinh(a(x - d_{eq}))}{\sinh(ad_{eq})}$$

$$J_z = aH_{ext} \frac{\cosh(ax)}{\sinh(ad_{eq})} - aH_{int} \frac{\cosh(a(x - d_{eq}))}{\sinh(ad_{eq})}$$

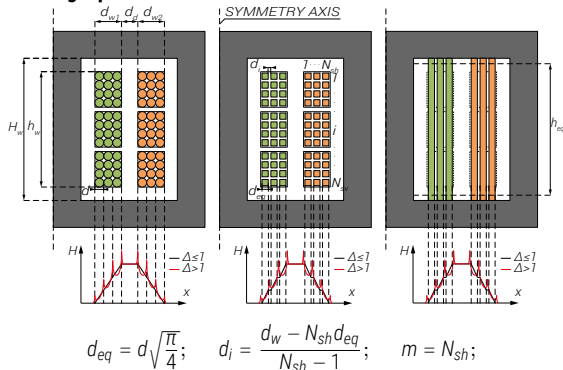
$$a = \frac{1+j}{\delta}; \quad \delta = \sqrt{\frac{\rho}{\pi \mu f}}$$

Foil Winding Loss Calculation:

$$P_{\sigma} = \frac{1}{\sigma} \int J J^* dv; \quad P_{\sigma} = I^2 \frac{L_w}{\delta \sigma h_w} m \left[\zeta_1 + \frac{2}{3} (m^2 - 1) \zeta_2 \right];$$

$$\zeta_1 = \frac{\sinh(2\Delta) + \sin(2\Delta)}{\cosh(2\Delta) - \cos(2\Delta)}; \quad \zeta_2 = \frac{\sinh(\Delta) - \sin(\Delta)}{\cosh(\Delta) + \cos(\Delta)}; \quad \Delta = \frac{d_{eq}}{\delta};$$

Winding Equivalence:



$$N_{sh} = \sqrt{\frac{N_s}{K_w}}; \quad N_{sv} = \sqrt{K_w N_s};$$

$$K_w = \frac{h_w}{d_w}$$

$$\Delta' = \sqrt{\eta} \Delta; \quad \eta = d_{eq} \frac{N_{sv}}{H_w};$$

MODELING: F-DEPENDENT LEAKAGE INDUCTANCE

Application of Dowell's Model on the Equivalent Foil Winding:

$$L_{\sigma} = N_1^2 \mu_0 \frac{l_w}{H_w} \left[\underbrace{\frac{d_{w1eq} m_{w1}}{3} F_{w1} + \frac{d_{w2eq} m_{w2}}{3} F_{w2}}_{\text{Frequency dependent portion due to the magnetic energy within the copper volume of the windings}} \right.$$

$$+ \underbrace{d_d}_{\text{Portion due to magnetic energy within the inter-winding dielectric volume}}$$

$$+ \underbrace{d_{w1i} \frac{(m_{w1} - 1)(2m_{w1} - 1)}{6m_{w1}}}_{\text{Portion due to magnetic energy within the inter-layer dielectric of the primary winding}}$$

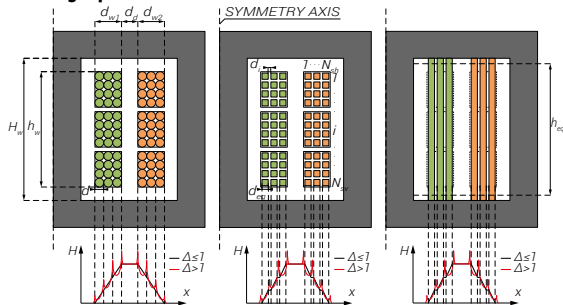
$$+ \left. \underbrace{d_{w2i} \frac{(m_{w2} - 1)(2m_{w2} - 1)}{6m_{w2}}}_{\text{Portion due to magnetic energy within the inter-layer dielectric of the secondary winding}} \right]$$

where:

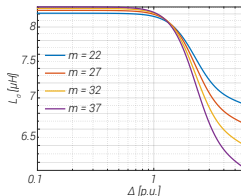
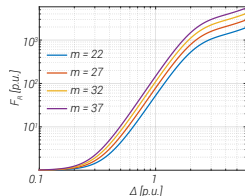
$$F_w = \frac{1}{2m^2 \Delta} \left[(4m^2 - 1)\varphi_1 - 2(m^2 - 1)\varphi_2 \right]$$

$$\varphi_1 = \frac{\sinh(2\Delta) - \sin(2\Delta)}{\cosh(2\Delta) - \cos(2\Delta)}; \quad \varphi_2 = \frac{\sinh(\Delta) - \sin(\Delta)}{\cosh(\Delta) - \cos(\Delta)}$$

Winding Equivalence:

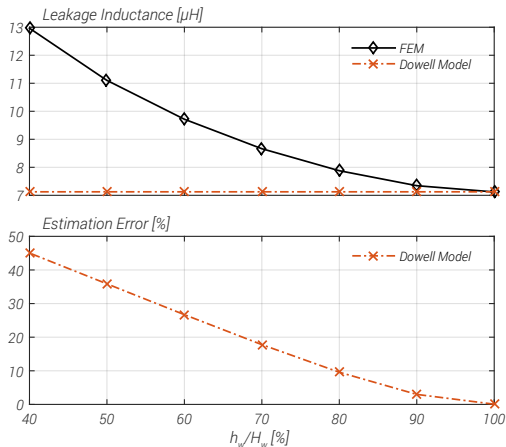
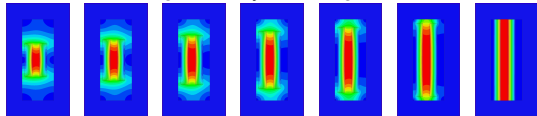


$$\Delta' = \sqrt{\eta} \Delta; \quad \eta = d_{eq} \frac{N_{SV}}{H_w}; \quad m = N_{sh}; \quad d_i = \frac{d_w - N_{sh} d_{eq}}{N_{sh} - 1};$$



MODELING: LEAKAGE INDUCTANCE (HYBRID MODEL)

Influence of Winding Geometry on Leakage inductance:



Hybrid Leakage Inductance Model [19]:

- ▶ Rogowski correction factor:

$$h_{eq} = \frac{h_w}{K_R}$$

$$K_R = 1 - \frac{1 - e^{-\pi h_w / (d_{w1} + d_d + d_{w2})}}{\pi h_w / (d_{w1} + d_d + d_{w2})}$$

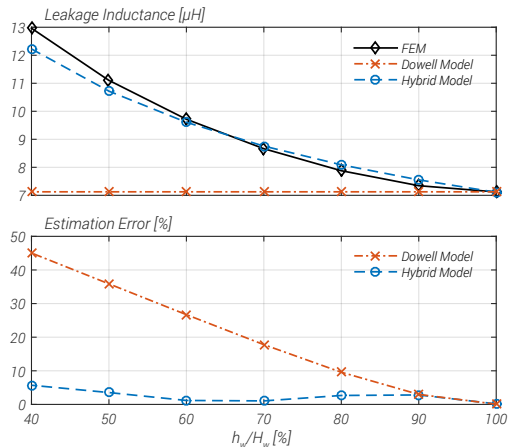
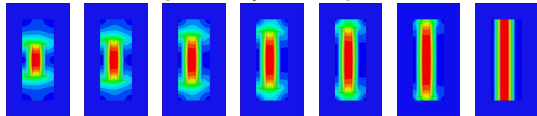
- ▶ Correction of Dowell's model ($H_w \rightarrow h_{eq}$):

$$L_\sigma = N_1^2 \mu_0 \frac{l_w}{H_w} \left[\frac{d_{w1eq} m_{w1}}{3} F_{w1} + \frac{d_{w2eq} m_{w2}}{3} F_{w2} + d_d \right. \\ \left. + d_{w1i} \frac{(m_{w1} - 1)(2m_{w1} - 1)}{6m_{w1}} + d_{w2i} \frac{(m_{w2} - 1)(2m_{w2} - 1)}{6m_{w2}} \right]$$

$$\Delta' = \sqrt{\eta} \Delta; \quad \eta = d_{eq} \frac{N_{sv}}{H_w}$$

MODELING: LEAKAGE INDUCTANCE (HYBRID MODEL)

Influence of Winding Geometry on Leakage inductance:



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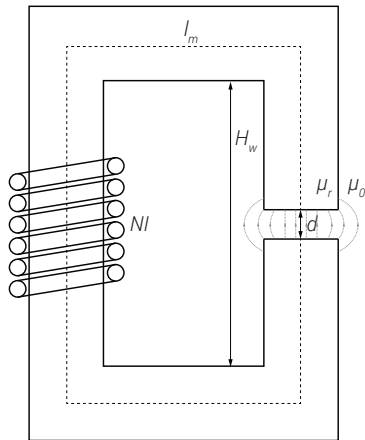
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$$L_\sigma = N_1^2 \mu_0 \frac{l_w}{h_{eq}} \left[\frac{d_{w1eq} m_{w1}}{3} F_{w1} + \frac{d_{w2eq} m_{w2}}{3} F_{w2} + d_d + d_{w1i} \frac{(m_{w1} - 1)(2m_{w1} - 1)}{6m_{w1}} + d_{w2i} \frac{(m_{w2} - 1)(2m_{w2} - 1)}{6m_{w2}} \right]$$

$$\Delta' = \sqrt{\eta} \Delta; \quad \eta = d_{eq} \frac{N_{sv}}{h_{eq}}$$

MODELING: MAGNETIZING INDUCTANCE

Magnetic Circuit with an Air-Gap:



Magnetizing Inductance Calculation:

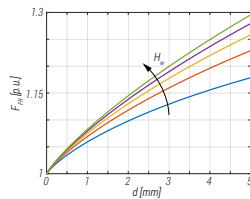
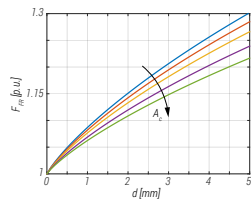
$$L_m = \frac{\mu_0 N^2 A_c}{\frac{l_m}{\mu_r} + d}$$

Air-Gap Calculation:

$$d = \mu_0 \frac{N^2 A_c}{L_m} - \frac{l_m}{\mu_r}$$

Fringing Effect:

$$L'_m = L_m F_{FR}; \quad F_{FR} = 1 + \frac{d}{\sqrt{A_c}} \ln \left(\frac{2H_w}{d} \right);$$

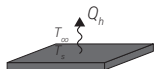


MODELING: HEAT-TRANSFER MECHANISMS

Conduction $Q_h = kA \frac{\Delta T}{L}$



Top:



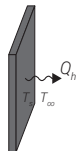
$$h = \frac{k(0.65 + 0.36Ra_L^{1/6})^2}{L}$$

$$L = \frac{\text{Area}}{\text{Perimeter}}$$

Convection
over
Hot-Plate

$$Q_h = hA(T_s - T_\infty)$$

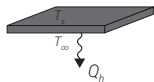
Side:



$$h = \frac{k}{L} \left(0.825 + \frac{0.387Ra_L^{1/6}}{(1 + (0.492/Pr)^9/16)^{8/27}} \right)^2$$

$L = \text{Height}$

Bottom:



$$h = \frac{k0.27Ra_L^{1/4}}{L}$$

$$L = \frac{\text{Area}}{\text{Perimeter}}$$

Radiation $Q_h = hA(T_1 - T_2)$



$$h = \varepsilon \sigma \frac{(T_1 + 273.15)^4 - (T_2 + 273.15)^4}{(T_1 - T_2)}$$

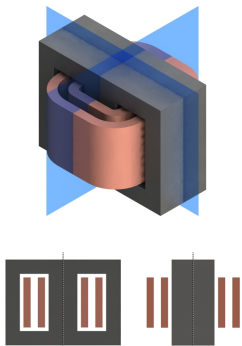
where: Ra_L - Rayleigh number, Pr - Prandtl number, ε - Emissivity, σ - Stefan-Boltzmann constant [20], [21], [22]

MODELING: THERMAL MODEL

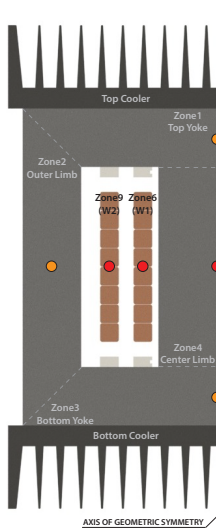
Modes Of Heat Transfer:

- ▶ Conduction
- ▶ Convection
- ▶ Radiation

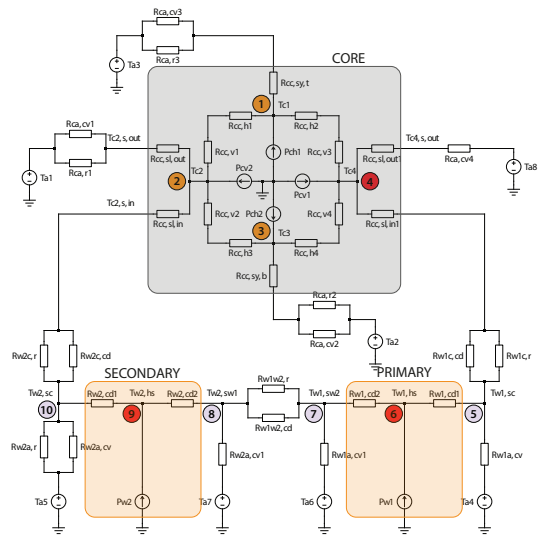
Planes of Symmetry:



Partitioning Into Zones:



Detailed Thermal Network Model [23]:

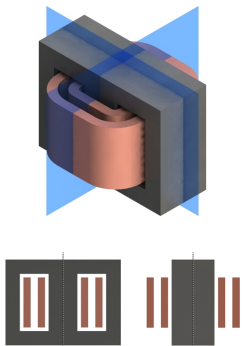


MODELING: THERMAL MODEL

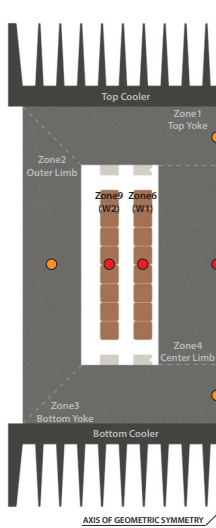
Modes Of Heat Transfer:

- ▶ Conduction
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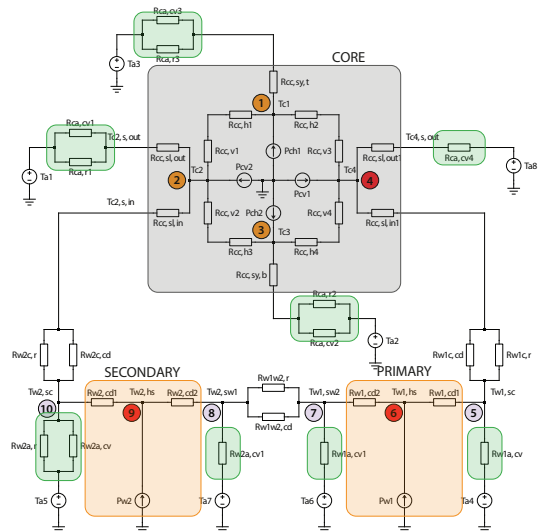
Planes of Symmetry:



Partitioning Into Zones:



Detailed Thermal Network Model [23]:

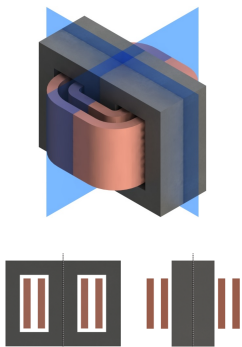


MODELING: THERMAL MODEL

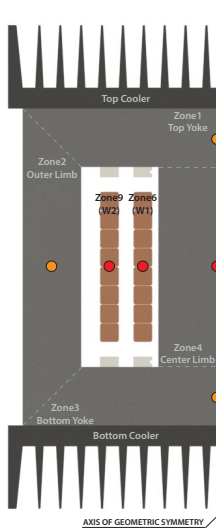
Modes Of Heat Transfer:

- ▶ Conduction
- ▶ Convection
- ▶ Radiation

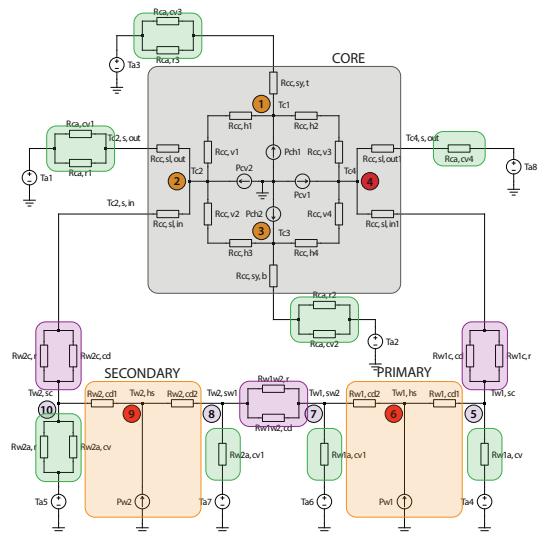
Planes of Symmetry:



Partitioning Into Zones:



Detailed Thermal Network Model [23]:



MODELING: THERMAL MODEL IMPLEMENTATION

Implementation of Thermal Network Model:

- Admittance Matrix:

$$Q_{(n)} = Y_{th(n \times n)} \Delta T_{(n)}$$

- Rearranging the nodes:

$$\begin{bmatrix} Q_{A(m)} \\ 0_{(p)} \end{bmatrix} = \begin{bmatrix} Y_{thAA(m \times m)} & Y_{thAB(m \times p)} \\ Y_{thBA(p \times m)} & Y_{thBB(p \times p)} \end{bmatrix} \begin{bmatrix} \Delta T_{A(m)} \\ \Delta T_{B(p)} \end{bmatrix}$$

- Kron reduction:

$$\Delta T_{A(m)} = \left(Y_{thAA(m \times m)} - Y_{thAB(m \times p)} Y_{thBB(p \times p)}^{-1} Y_{thBA(p \times m)} \right)^{-1} Q_{A(m)}$$

$$\Delta T_{A(m)} = Y_{Kron(m \times m)}^{-1} Q_{A(m)}$$

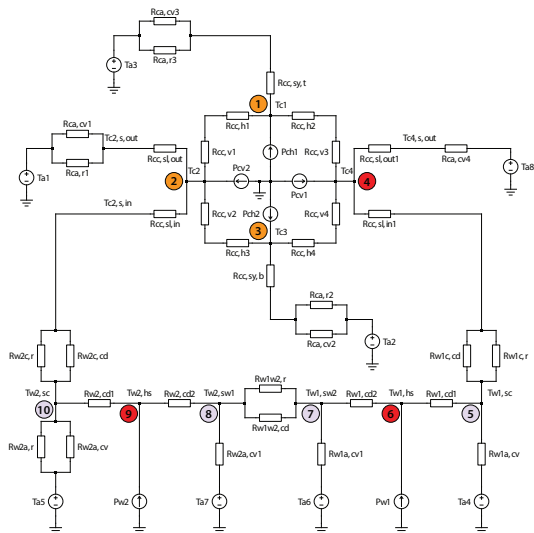
- Kron matrix:

$$Y_{Kron(m \times m)} = Y_{thAA(m \times m)} - Y_{thAB(m \times p)} Y_{thBB(p \times p)}^{-1} Y_{thBA(p \times m)}$$

Analytical Model Results for the optimal MFT prototype:

$T_1 [^{\circ}C]$	$T_2 [^{\circ}C]$	$T_3 [^{\circ}C]$	$T_4 [^{\circ}C]$	$T_6 [^{\circ}C]$	$T_9 [^{\circ}C]$
51.3	59.9	58.4	73.75	124.6	116.3

Detailed Thermal Network Model [23]:



MODELING: THERMAL FEM ANALYSIS AND VERIFICATION

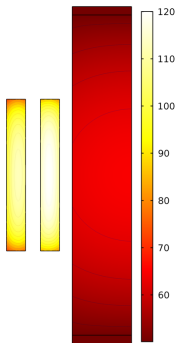
Results:

- ▶ Different cooling conditions inside and outside of core window
- ▶ High thermal conduction equalizes the temp along the conductors
- ▶ Full 3D model estimations correlate well with analytical ones

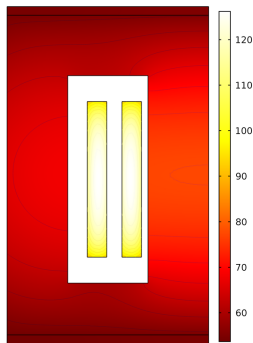
Hot-Spot Temperature Estimation Comparison:

Hot-spot nodes	T_1 [$^{\circ}\text{C}$]	T_2 [$^{\circ}\text{C}$]	T_3 [$^{\circ}\text{C}$]	T_4 [$^{\circ}\text{C}$]	T_6 [$^{\circ}\text{C}$]	T_9 [$^{\circ}\text{C}$]
FEM 2D detail 1	/	/	/	70	120	106
FEM 2D detail 2	/	/	/	76	127	125
FEM 3D full	/	/	/	75	122	113
Analytical	51.3	59.9	58.4	73.75	124.6	116.3

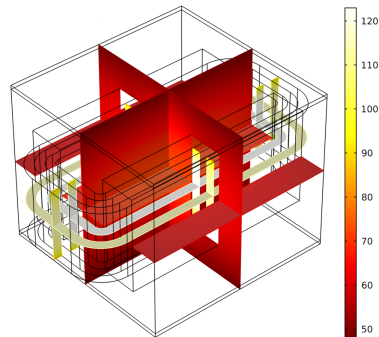
2D symmetry detail 1:



2D symmetry detail 2:



Full 3D model:





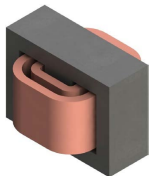
MFT DESIGN OPTIMIZATION

Brute force academic example? You may do it differently!

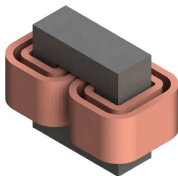
SELECTED TECHNOLOGIES AND MATERIALS

Construction Choices:

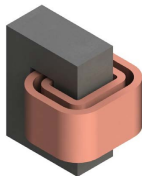
► MFT Types



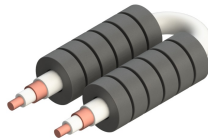
Shell Type



Core Type



C-Type



Coaxial Type

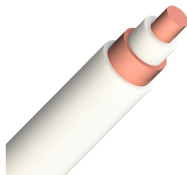
► Winding Types



Litz Wire



Foil



Coaxial



Hollow

Materials:

► Magnetic Materials

- Silicon Steel
- Amorphous
- Nanocrystalline
- **Ferrites**

► Windings

- **Copper**
- Aluminum

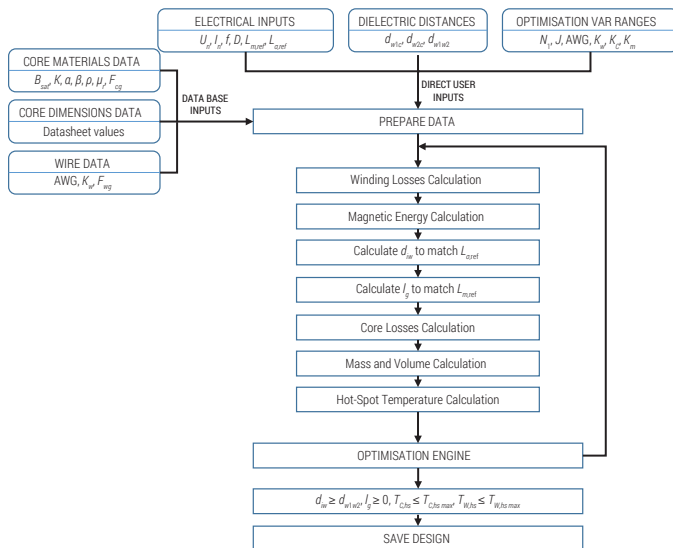
► Insulation

- **Air**
- Solid
- Oil

► Cooling

- **Air natural/forced**
- Oil natural/forced
- Water

DESIGN OPTIMIZATION: ALGORITHM



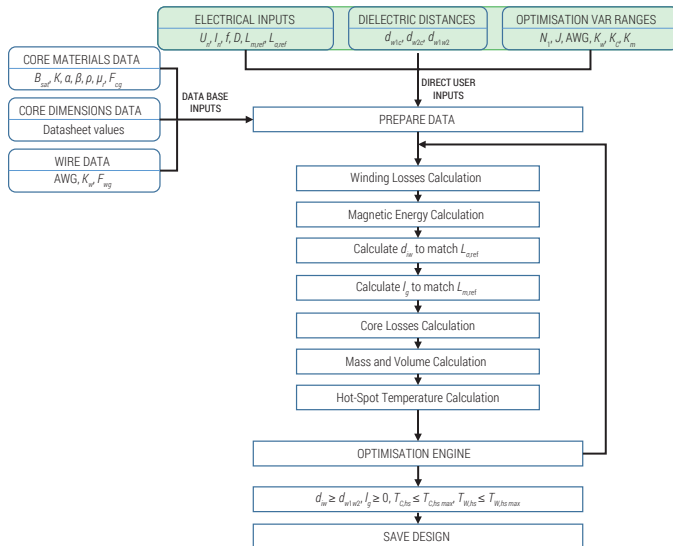
▲ MFT design optimization algorithm

Algorithm Specifications:

- ▶ Used Software Platform:
 - ▶ MathWorks MATLAB
- ▶ Used Hardware Platform:
 - ▶ Laptop PC (i7-2.1GHz, 8GB RAM)
- ▶ Performance Measure:
 - ▶ 59000 designs are generated in less than 190 seconds
- ▶ Electrical Specifications:

P_n	100kW	f_{sw}	10kHz
V_1	750V	V_2	750V
$L_{\sigma 1,2}$	3.27μH	L_m	1.8mH

DESIGN OPTIMIZATION: ALGORITHM



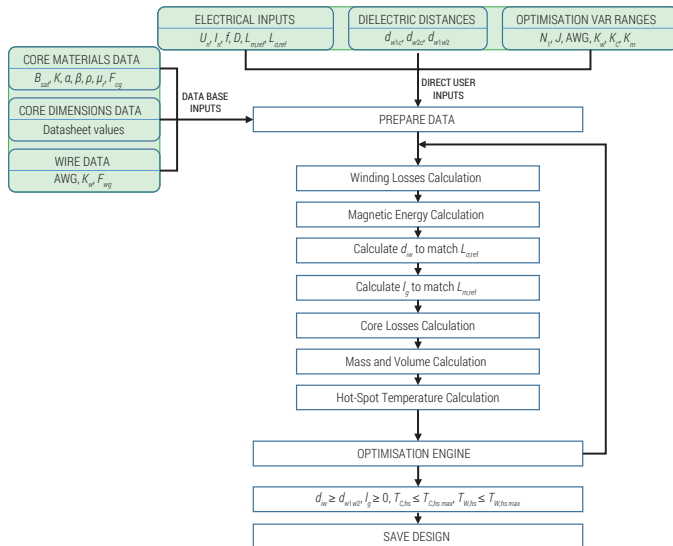
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DESIGN OPTIMIZATION: ALGORITHM



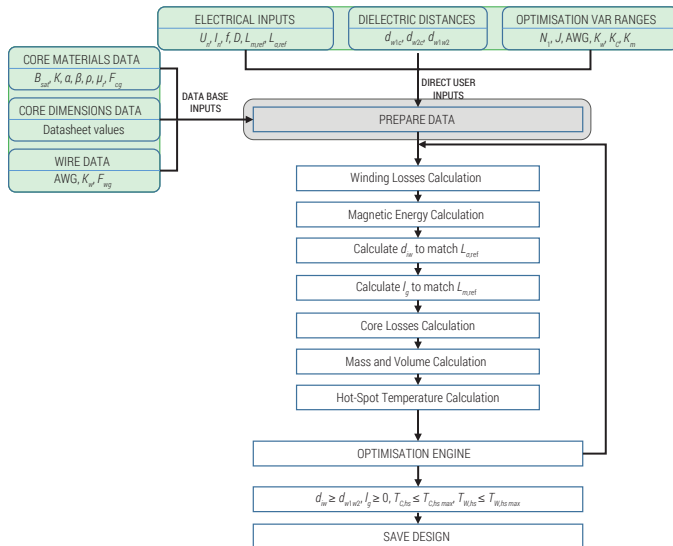
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DESIGN OPTIMIZATION: ALGORITHM



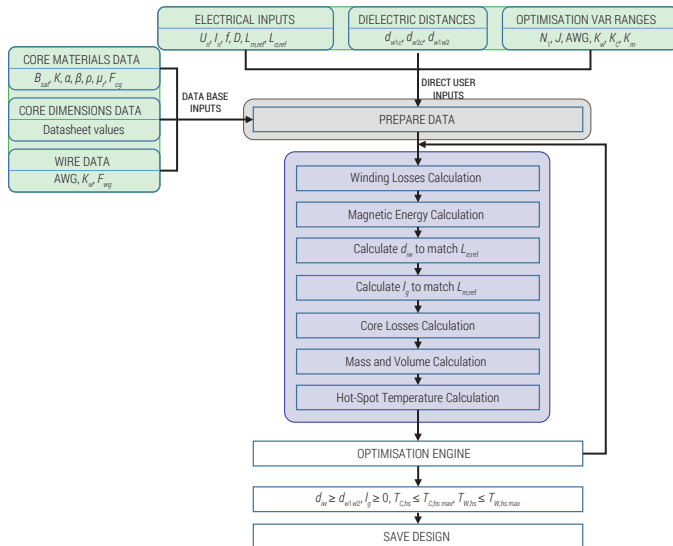
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DESIGN OPTIMIZATION: ALGORITHM



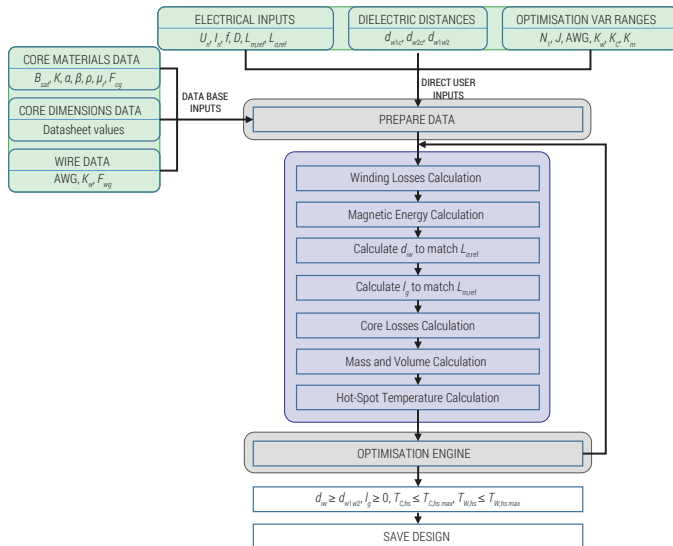
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DESIGN OPTIMIZATION: ALGORITHM



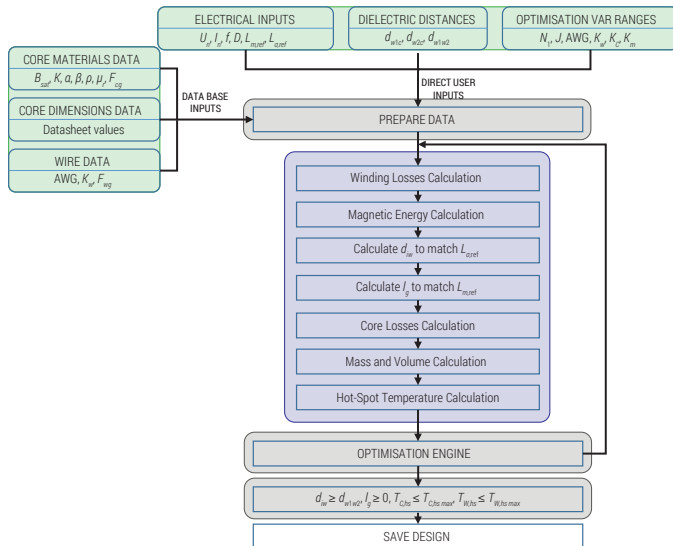
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DESIGN OPTIMIZATION: ALGORITHM



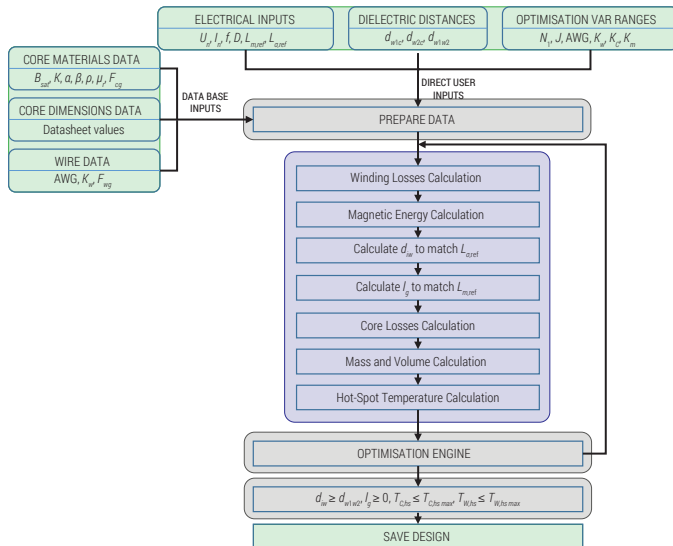
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DESIGN OPTIMIZATION: ALGORITHM



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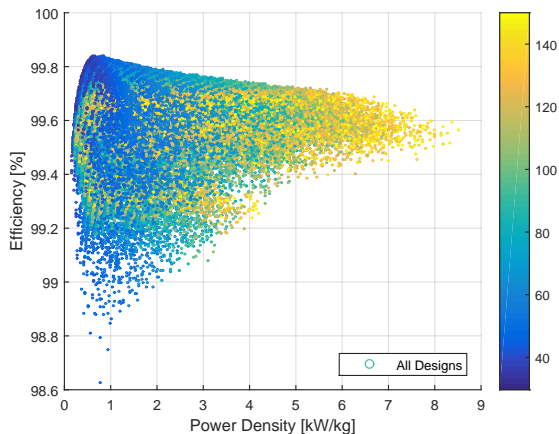
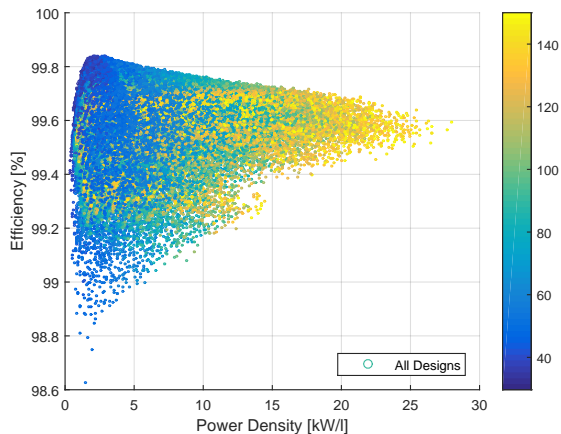
DESIGN OPTIMIZATION: RESULTS

Applied Filters:

T_{Wmax} [$^{\circ}C$]	T_{Cmax} [$^{\circ}C$]	V_{max} [V]	M_{max} [kg]	η_{min} [%]
150	100	/	/	/

Number of Designs:

► More than 1.8 Million



▲ Generated designs: left: Efficiency vs V-density; right: Efficiency vs W-density. Color code indicates hot-spot temperature

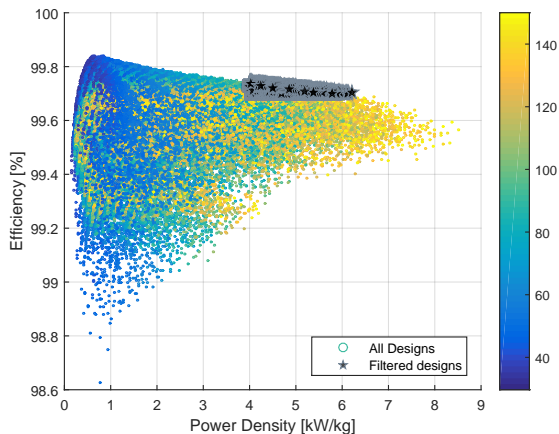
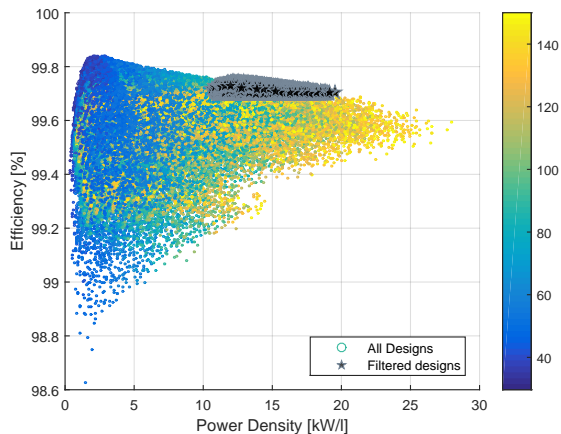
DESIGN OPTIMIZATION: RESULTS

Applied Filters:

T_{Wmax} [$^{\circ}C$]	T_{Cmax} [$^{\circ}C$]	V_{max} [V]	M_{max} [kg]	η_{min} [%]
150	100	12	25	99.7

Number of Designs:

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▲ Generated designs: left: Efficiency vs V-density; right: Efficiency vs W-density. Color code indicates hot-spot temperature

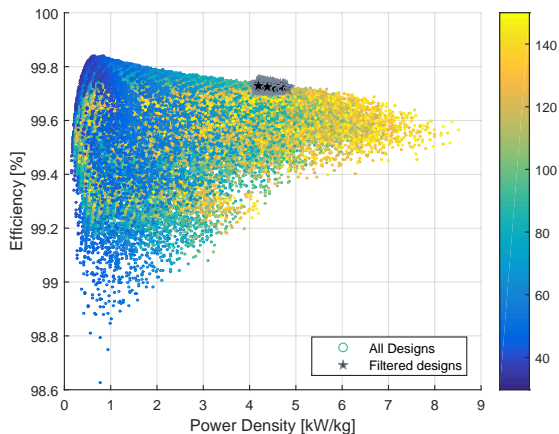
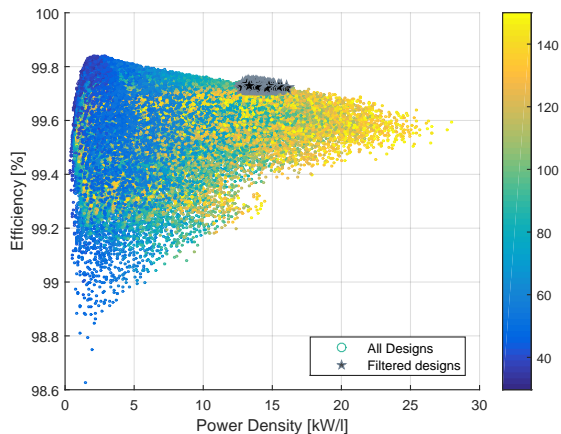
DESIGN OPTIMIZATION: RESULTS

Applied Filters:

T_{Wmax} [$^{\circ}C$]	T_{Cmax} [$^{\circ}C$]	V_{max} [V]	M_{max} [kg]	η_{min} [%]
130	80	9	24	99.72

Number of Designs:

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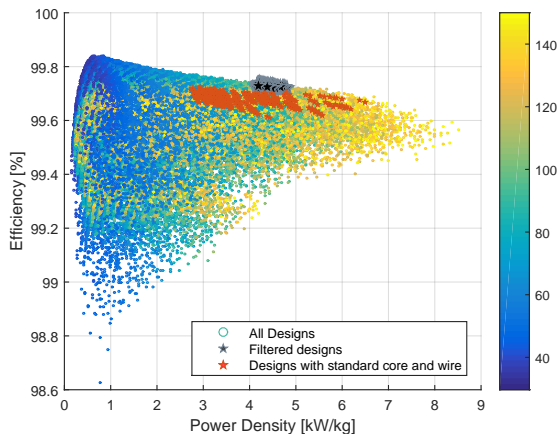
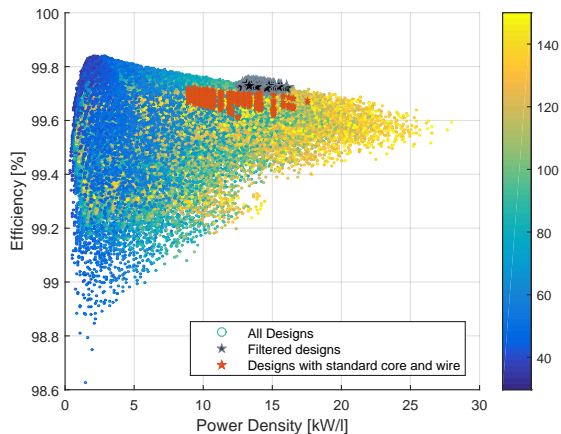
DESIGN OPTIMIZATION: RESULTS

Applied Filters:

T_{Wmax} [$^{\circ}C$]	T_{Cmax} [$^{\circ}C$]	V_{max} [V]	M_{max} [kg]	η_{min} [%]
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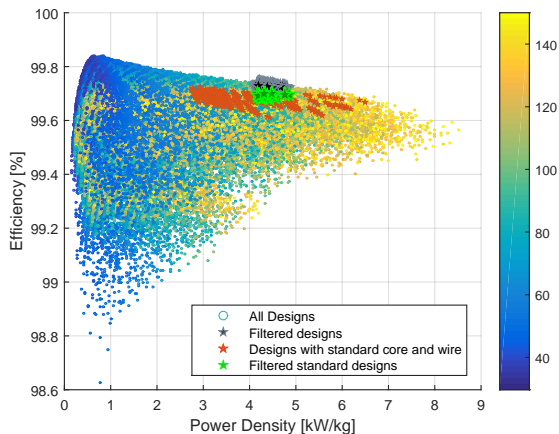
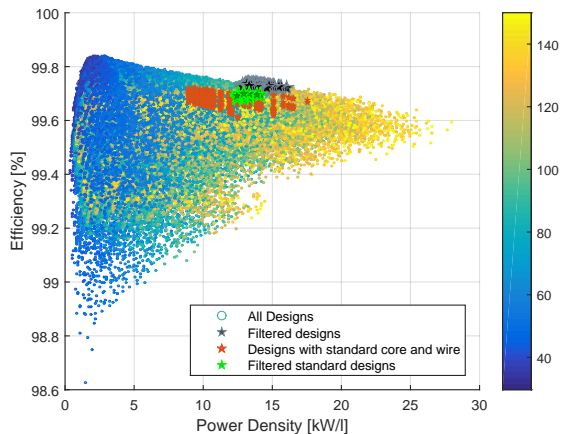
DESIGN OPTIMIZATION: RESULTS

Applied Filters:

T_{Wmax} [$^{\circ}C$]	T_{Cmax} [$^{\circ}C$]	V_{max} [V]	M_{max} [kg]	η_{min} [%]
135	80	10	24	99.6

Number of Designs:

► More than 1.8 Million



▲ Generated designs: left: Efficiency vs V-density; right: Efficiency vs W-density. Color code indicates hot-spot temperature

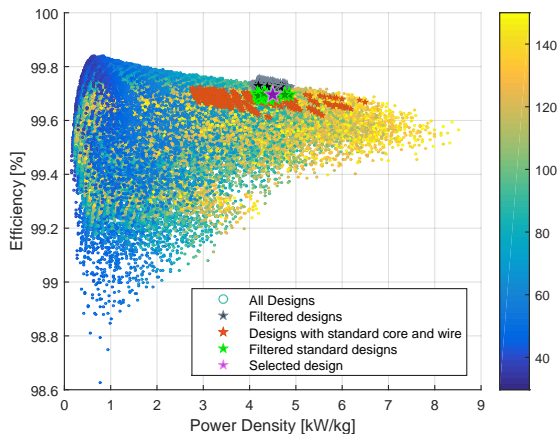
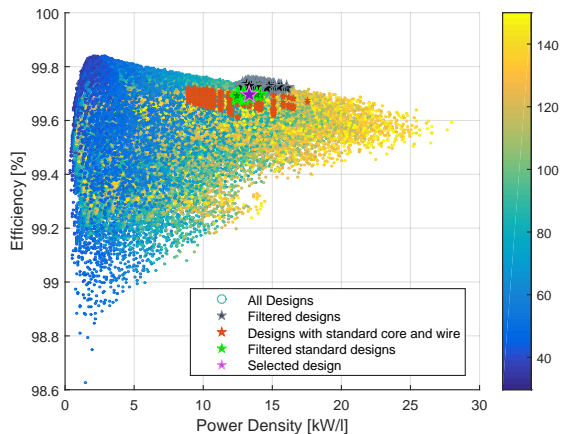
DESIGN OPTIMIZATION: RESULTS

Applied Filters:

T_{Wmax} [$^{\circ}C$]	T_{Cmax} [$^{\circ}C$]	V_{max} [V]	M_{max} [kg]	η_{min} [%]
135	80	10	24	99.6

Number of Designs:

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▲ Generated designs: left: Efficiency vs V-density; right: Efficiency vs W-density. Color code indicates hot-spot temperature



100kW, 10kHz MFT PROTOTYPE

Assembly, testing and design tool verification!

MFT PROTOTYPE: DESIGN ASSEMBLY



Optimal MFT Design 3D-CAD



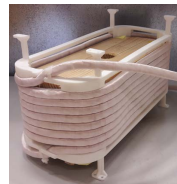
Coil-Formers 3D-CAD



Coil-Formers 3D-Print



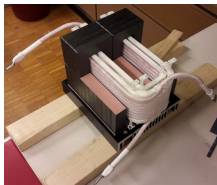
Primary Winding



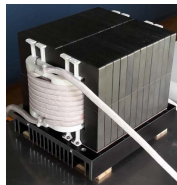
Secondary Winding



Core Assembly



MFT Assembly 1



MFT Assembly 2



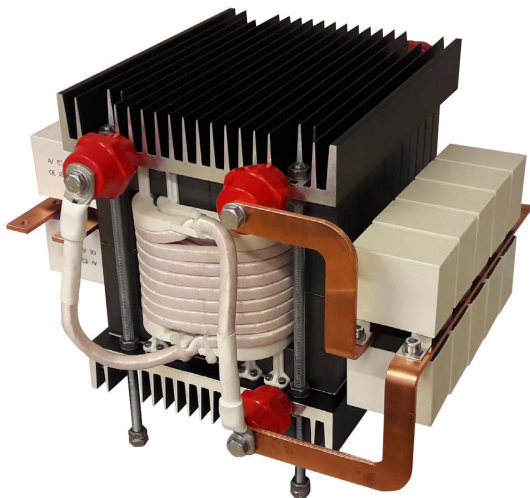
Litz-Wire Termination



MFT Prototype

CONVERTER READY MFT

MFT Prototype



▲ 100kW, 10kHz MFT including resonant capacitors

Prototype Specifications:

- ▶ Core:
 - ▶ 12 stacks of 4 x SiFERRITE U-Cores (UU9316 - CF139)
- ▶ Windings:
 - ▶ 8-Turns
 - ▶ Square Litz Wire (8.7x8.7mm, 1400 strands, AWG 32, 43.69mm²)
- ▶ Coil-Formers:
 - ▶ Additive manufacturing process (3-D printing)
 - ▶ High strength thermally resistant plastic (PA2200)
- ▶ Resonant Capacitor Banks:
 - ▶ (7x5μF + 1x2.5μF) AC film capacitors in parallel
 - ▶ Custom designed copper bus-bars

Electrical Ratings:

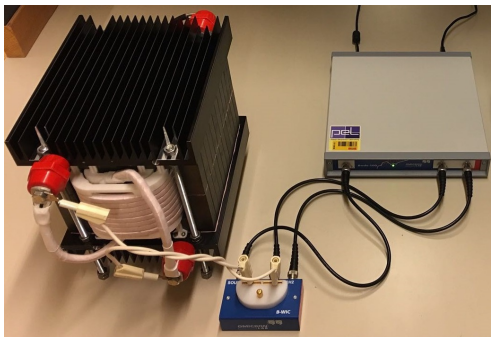
P_n	100kW	V_1	750V	$L_{\sigma 1,2}$	4.2μH
f_{sw}	10kHz	V_2	750V	L_m	750μH

MEASUREMENTS: ELECTRIC PARAMETERS

Measurement of Electric Parameters:

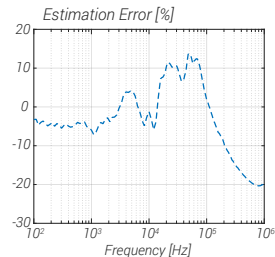
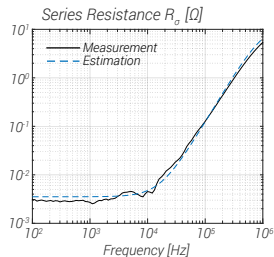
- ▶ Network Analyzer Bode100
- ▶ Impedance Measurement
- ▶ Results at 10kHz: $L_\sigma = 8.4\mu\text{H}$, $L_m = 750\mu\text{H}$, $R_\sigma = 0.2\mu\Omega$

LV Measurement Setup:

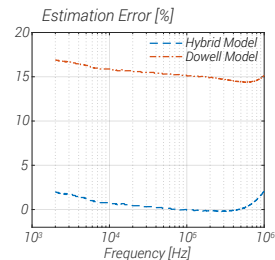
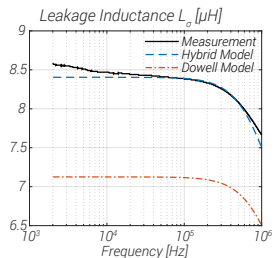


- ▲ Electrical measurements using Bode100

Series Resistance Measurement:



Leakage Inductance Measurement:

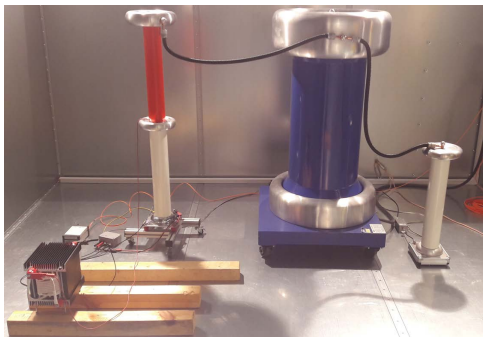


MEASUREMENTS: DIELECTRIC PARAMETERS

Dielectric Withstand Test:

- ▶ Partial Discharge measurement between all conductive parts
- ▶ High Voltage 50Hz source within a Faraday cage
- ▶ 10pC - between primary and secondary winding at 4kV

HV Measurement Setup:

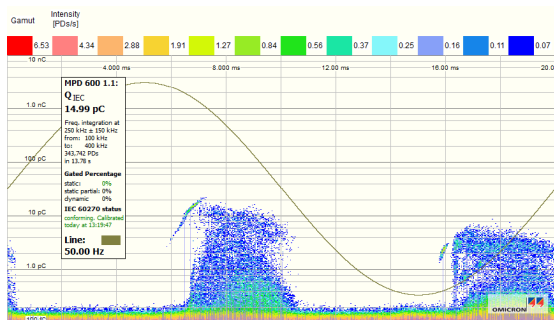


▲ MFT during AC test

PD Test Settings:

- ▶ Front of the voltage profile: $V = 6kV$
- ▶ Flat back of the voltage profile: $V = 4kV$
- ▶ Peak PD at periods where $|dV/dt|$ increases after the V peak
- ▶ PD is influenced by combination of V and $|dV/dt|$

Measured PD at flat back $V = 4kV$:

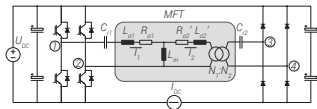


▲ MPD600 obtained measurement results

MEASUREMENTS: LOAD TEST

Test Setup Topology:

- ▶ B2B Resonant Converter
- ▶ Input voltage maintained by U_{DC}
- ▶ Power circulation via I_{DC}

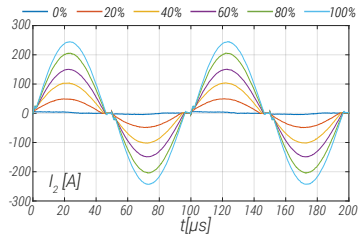
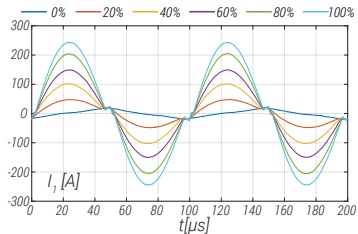
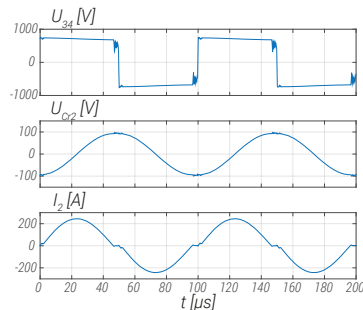
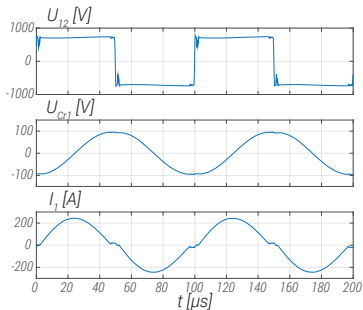


Test Setup:



- ▶ B2B MFT test setup

Measurement Results:



- ▶ Experimental results: left: MFT primary waveforms; right: MFT secondary waveforms

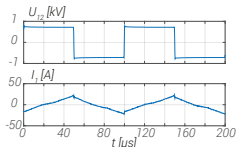
MEASUREMENTS: THERMAL RUN

Measurement Setup:

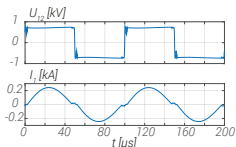


Thermal Run:

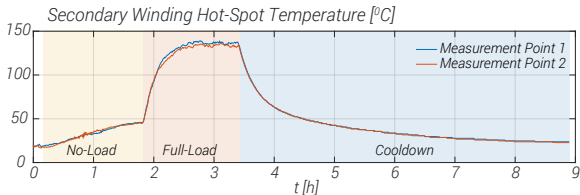
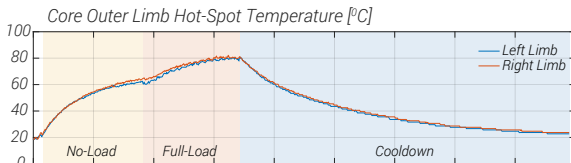
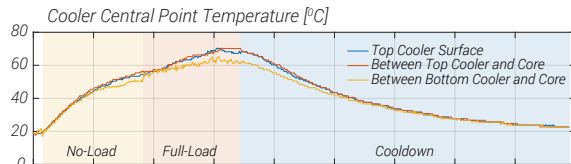
▶ No-Load Operation:



▶ Full-Load Operation:



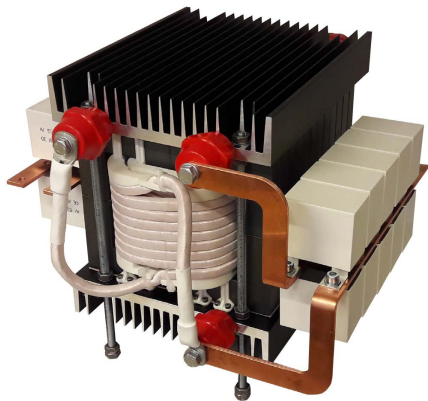
Thermal Profile:



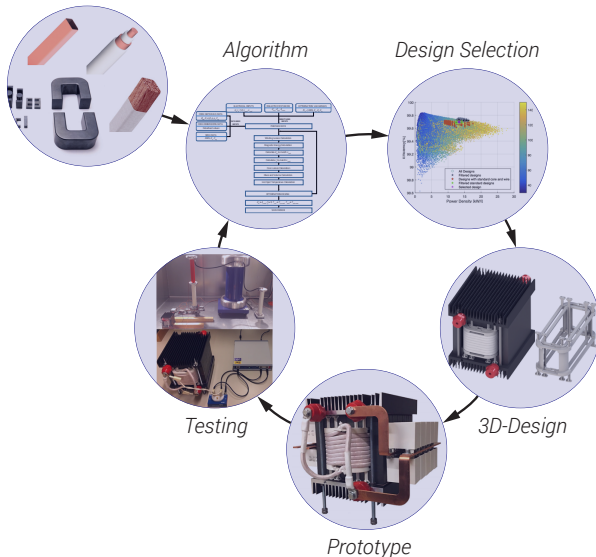
▶ Thermal heat run results

CONCLUSION

- ▶ Complex and challenging design optimization
- ▶ Large number of available materials
- ▶ Customized designs prevail
- ▶ Research opportunities...

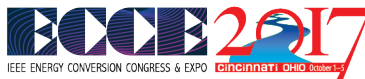
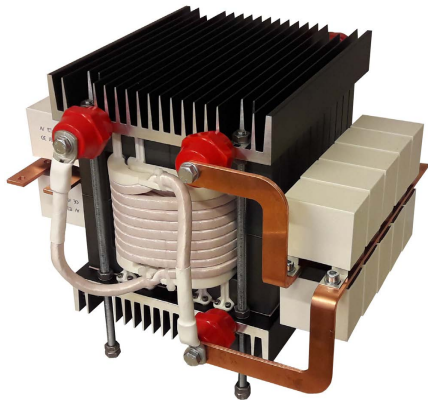


Components & Materials



CONCLUSION

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- ▶ Large number of available materials
- ▶ Customized designs prevail
- ▶ Research opportunities...



BIOGRAPHIES



Drazen Dujic is an Assistant Professor and Head of the Power Electronics Laboratory at EPFL. He received the Dipl.Ing. and MSc degrees from the University of Novi Sad, Novi Sad, Serbia in 2002 and 2005, respectively, and the PhD degree from Liverpool John Moores University, Liverpool, UK in 2008. From 2003 to 2006, he was a Research Assistant with the Faculty of Technical Sciences at University of Novi Sad. From 2006 to 2009, he was a Research Associate with Liverpool John Moores University. After that he moved to industry and joined ABB Switzerland Ltd, where from 2009 to 2013, he was Scientist and then Principal Scientist with ABB Corporate Research Center in Baden-Dättwil, and from 2013 to 2014 he was R&D Platform Manager with ABB Medium Voltage Drives in Turgi. He is with EPFL since 2014.

His research interests include the areas of design and control of advanced high power electronic systems and high-performance drives, predominantly for the medium voltage applications related to electrical energy generation, conversion and storage. He has authored or co-authored more than 100 scientific publications and has filed twelve patents.

In 2018 he received EPE Outstanding Service Award from European Power Electronics and Drives Association (EPE) and 2014 The Isao Takahashi Power Electronics Award for Outstanding Achievement in Power Electronics. He is Senior Member of IEEE, EPE Member, and serves as Associate Editor for IEEE Transactions on Power Electronics, IEEE Transactions on Industrial Electronics and IET Electric Power Applications.



Marko Mogorovic received the Dipl.Ing. degree from the University of Belgrade, Belgrade, Serbia, in 2013 and MSc degree from the École polytechnique fédérale de Lausanne (EPFL), Lausanne, Switzerland, in 2015. Currently, he is about to obtain the Ph.D. degree at Power Electronics Laboratory at EPFL, Lausanne, Switzerland. His current research focus is on the design optimization of the high power medium frequency transformers for medium voltage applications and emerging solid state transformers.

He is an IEEE Student Member.

Material presented in the webinar has been developed during his PhD research project.

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MEDIUM FREQ. TRANSFORMER DESIGN OPTIMIZATION FOR SOLID STATE TRANSFORMERS

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